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(12) **United States Design Patent**
Abare et al.

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(54) **LIGHT EMITTING DIODE (LED) PACKAGE**

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(73) Assignee: **Cree, Inc.**, Durham, NC (US)

(**) Term: **14 Years**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180; D26/1; 257/79, 80, 81, 88, 257/89, 95, 98, 99, 100, E33.058; 313/483, 313/498, 500; 362/555, 800
See application file for complete search history.

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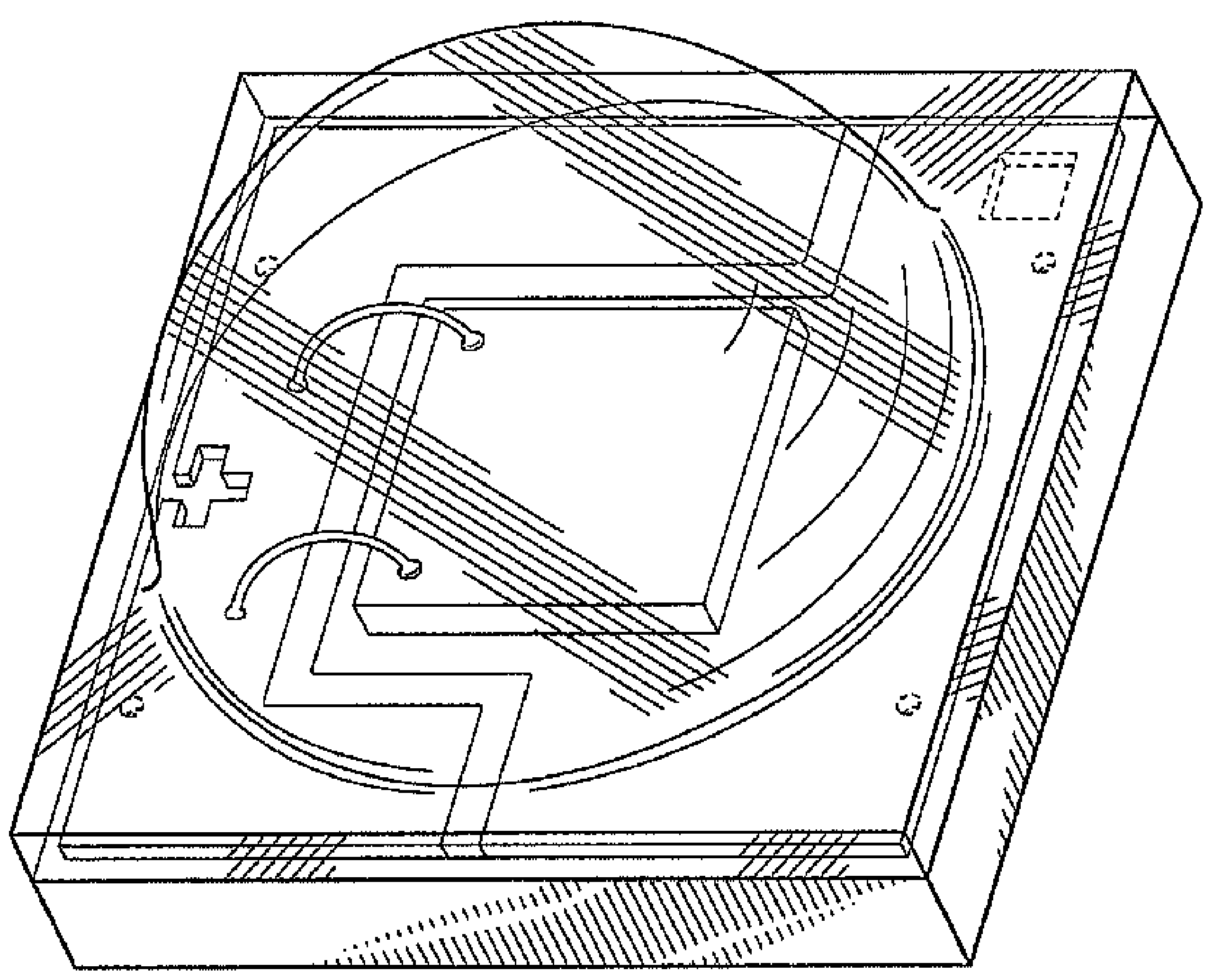

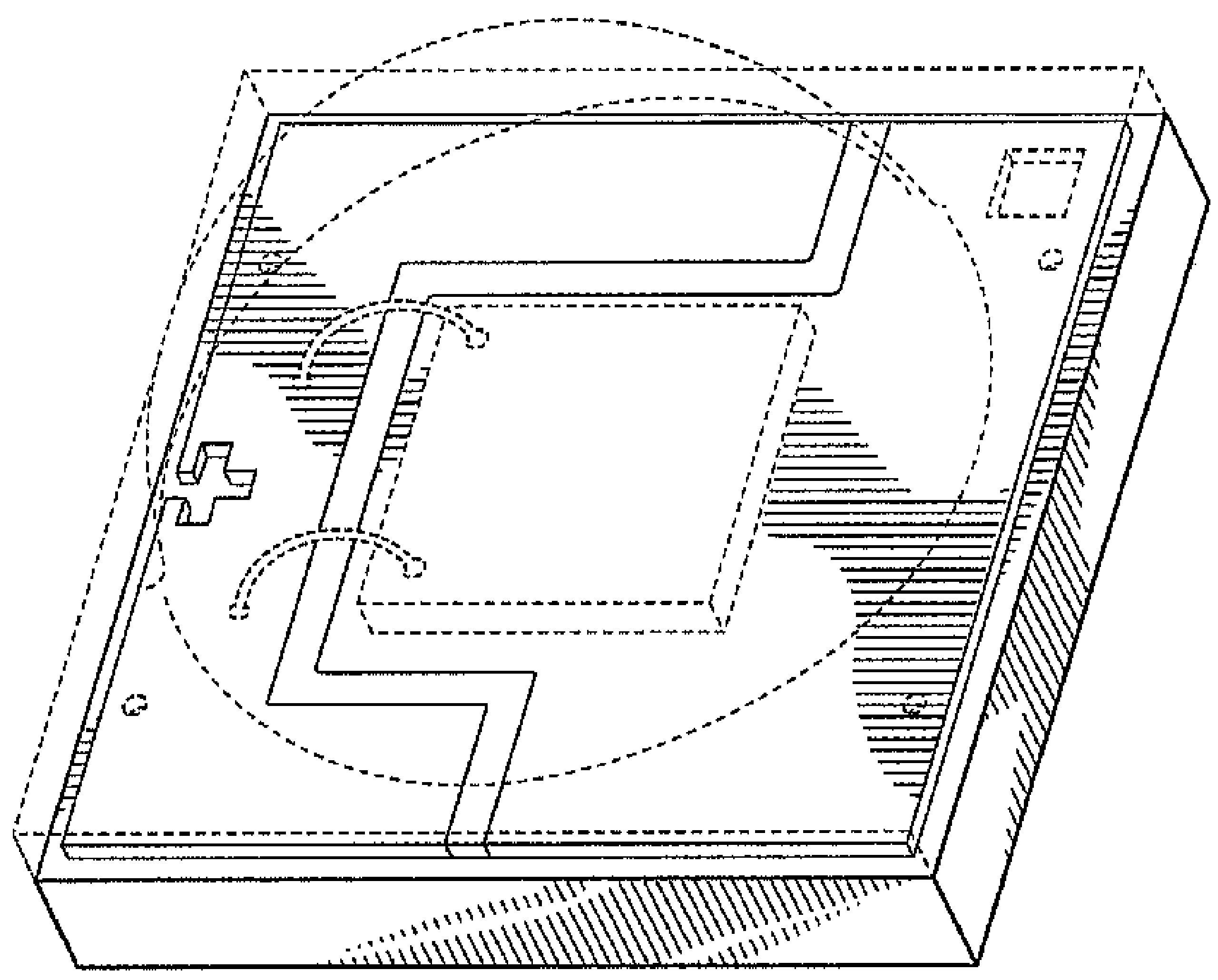

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(74) *Attorney, Agent, or Firm* — Jenkins, Wilson, Taylor & Hunt, P.A.

(57) CLAIM

The ornamental design for a light emitting diode (LED) package, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a LED package showing our design according to a first embodiment;
FIG. **2** is a top plan view thereof;
FIG. **3** is a bottom plan view thereof, opposite the view of FIG. **2**;
FIG. **4** is a first side view thereof;
FIG. **5** is a second side view thereof;
FIG. **6** is a third side view thereof, opposite the view of FIG. **4**;
FIG. **7** is a fourth side view thereof, opposite the view of FIG. **5**;
FIG. **8** is a top perspective view of a LED package showing our design according to a second embodiment;
FIG. **9** is a top plan view thereof;
FIG. **10** is a bottom plan view thereof, opposite the view of FIG. **9**;
FIG. **11** is a first side view thereof;
FIG. **12** is a second side view thereof;
FIG. **13** is a third side view thereof, opposite the view of FIG. **11**;
FIG. **14** is a fourth side view thereof, opposite the view of FIG. **12**;
FIG. **15** is a top perspective view of a LED package showing our design according to a third embodiment;
FIG. **16** is a top plan view;
FIG. **17** is a bottom plan view;
FIG. **18** is first side view;
FIG. **19** is second side view;
FIG. **20** is third side view;
FIG. **21** is fourth side view;
FIG. **22** is a top perspective view of a LED package showing our design according to a fourth embodiment;
FIG. **23** is a top plan view;
FIG. **24** is a bottom plan view;
FIG. **25** is first side view;
FIG. **26** is second side view;
FIG. **27** is third side view; and,
FIG. **28** is fourth side view.

The broken lines are for illustrative purposes only and form no part of the claimed design. The stippled portion of the embodiment illustrated in FIGS. **8**, **9**, **11**, and **13** represent that the stippled portion is a different material than other, adjacent portions. The more densely stippled portions illustrated in FIGS. **22**, **23**, and **25**-**28** represent a metallic surface.

1 Claim, 24 Drawing Sheets

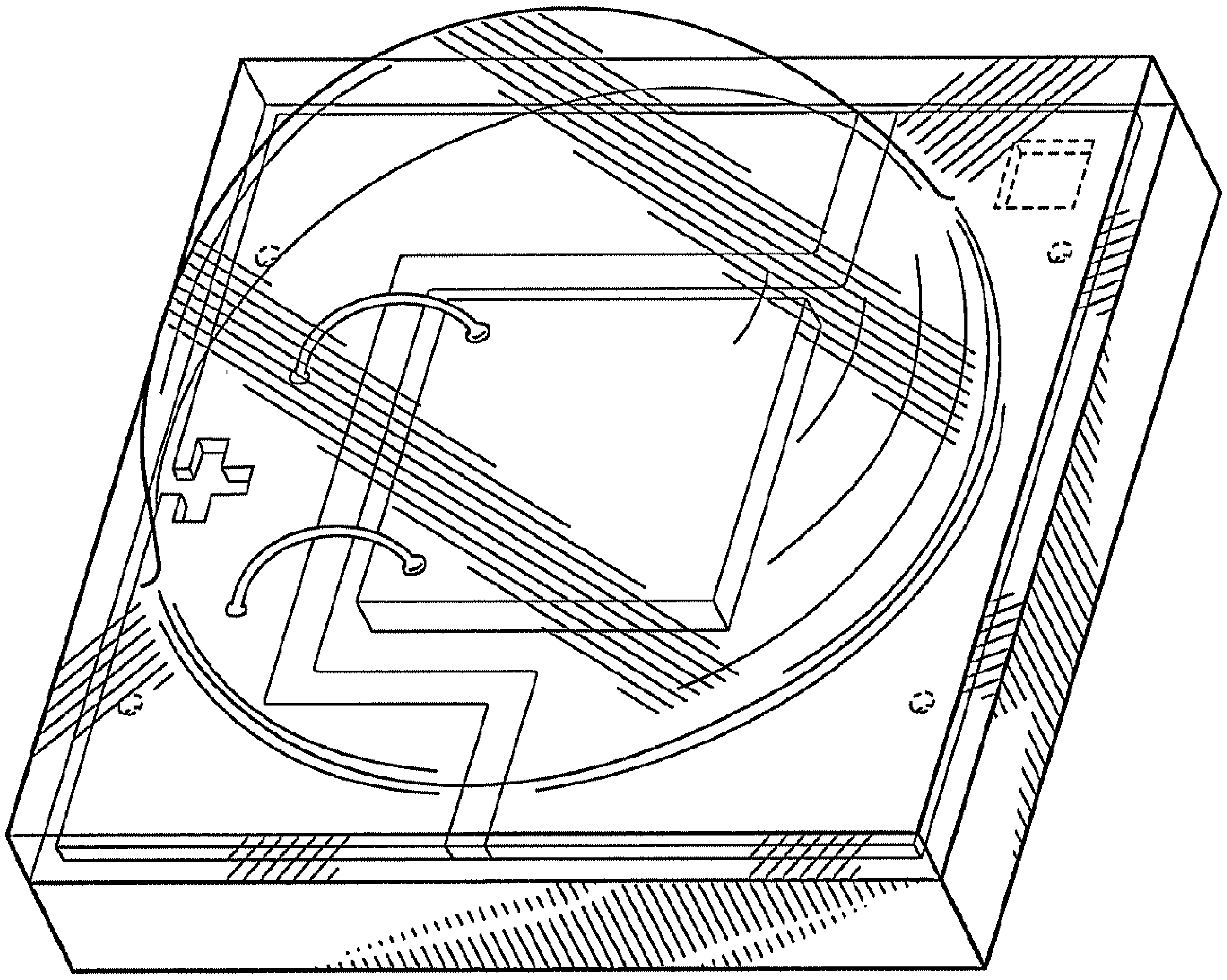


FIG. 1

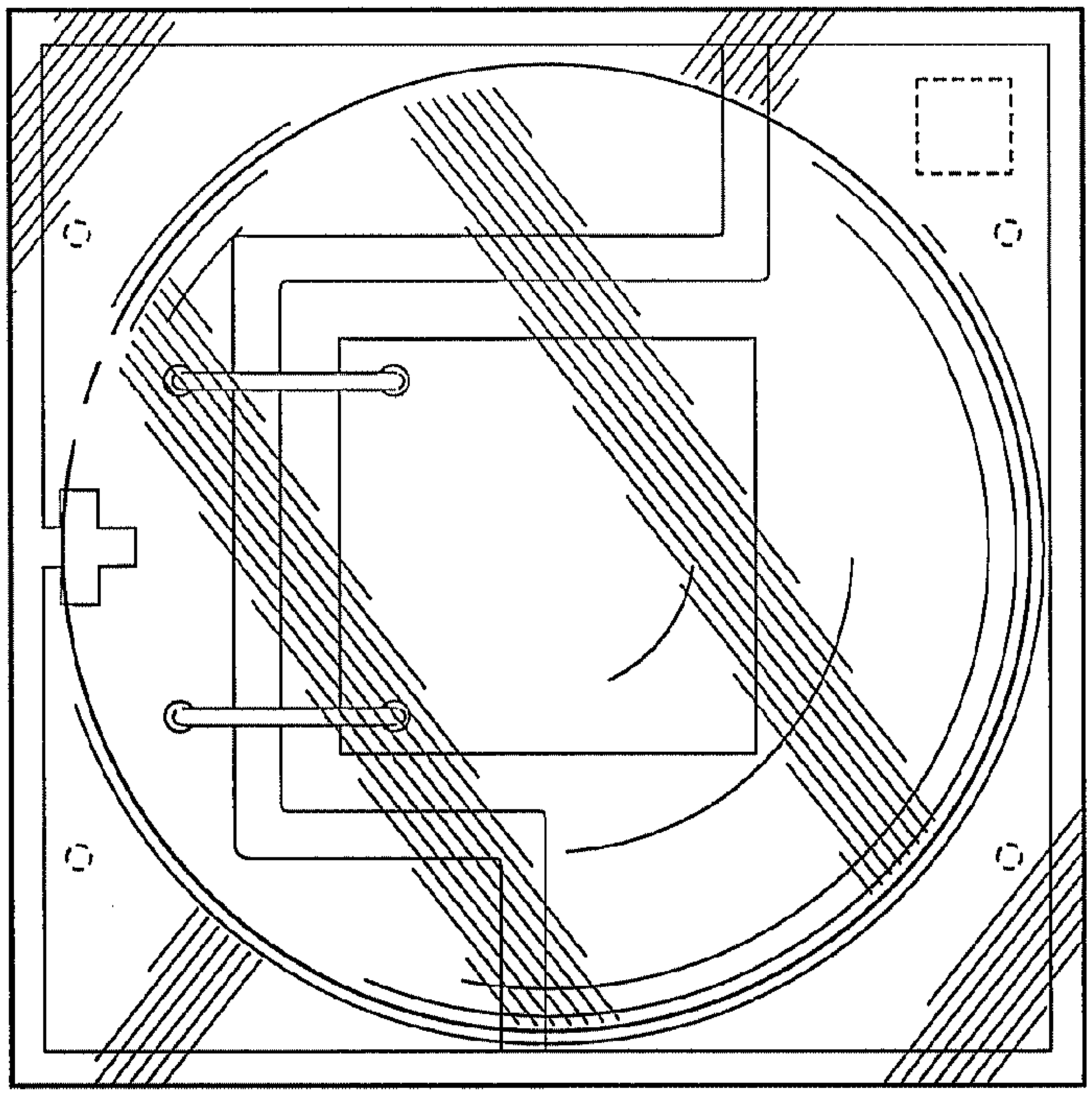


FIG. 2

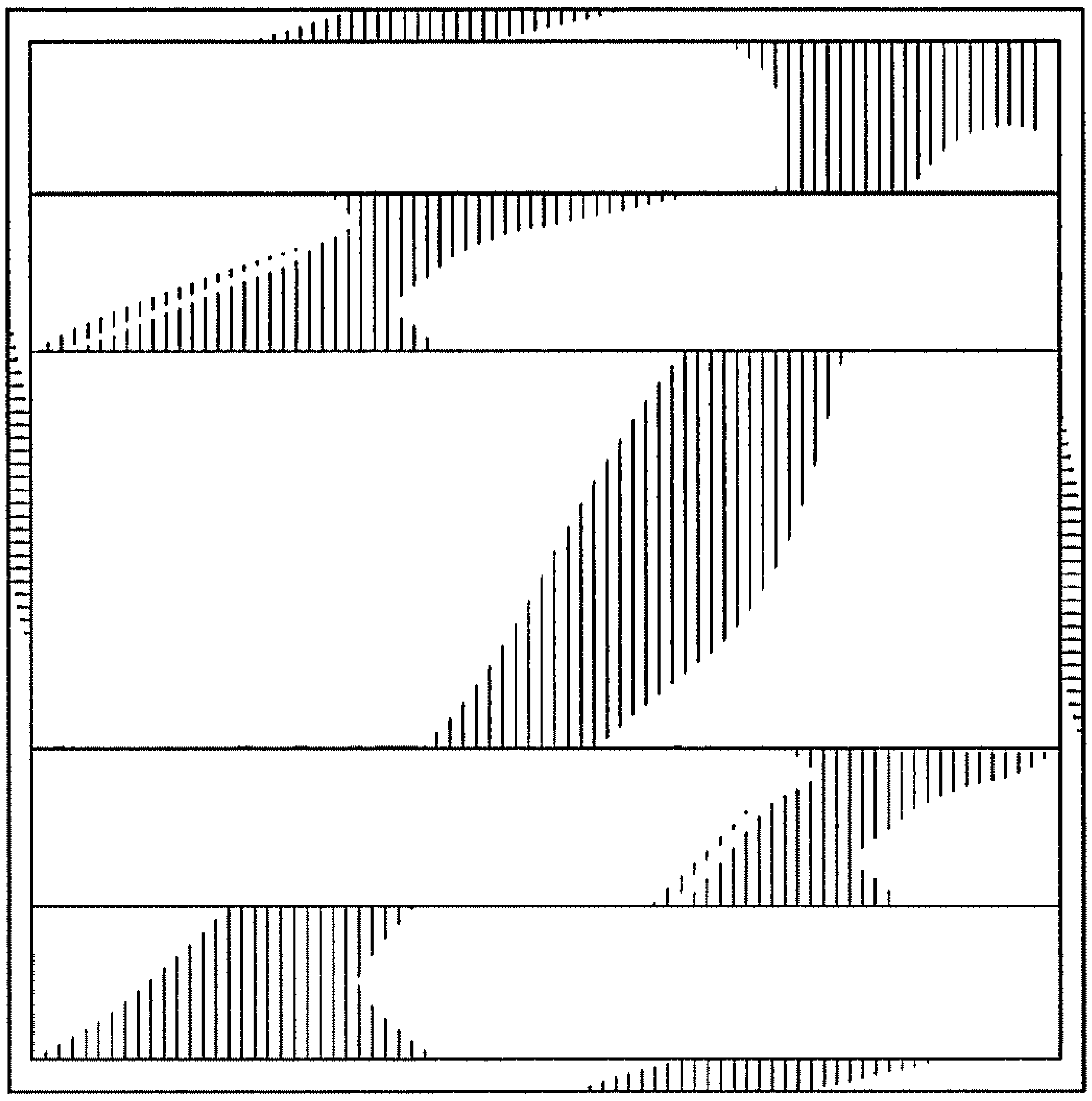


FIG. 3

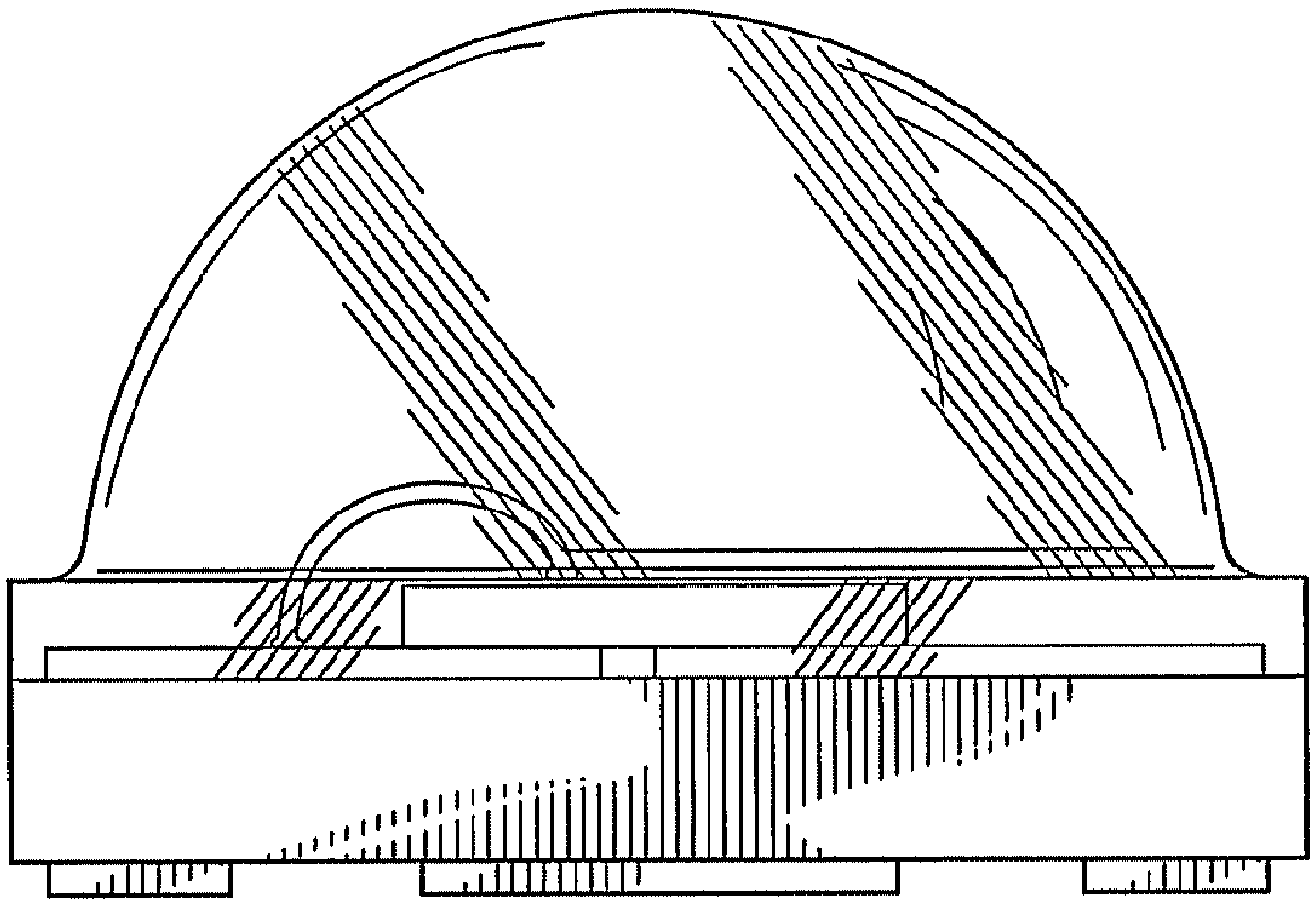


FIG. 4

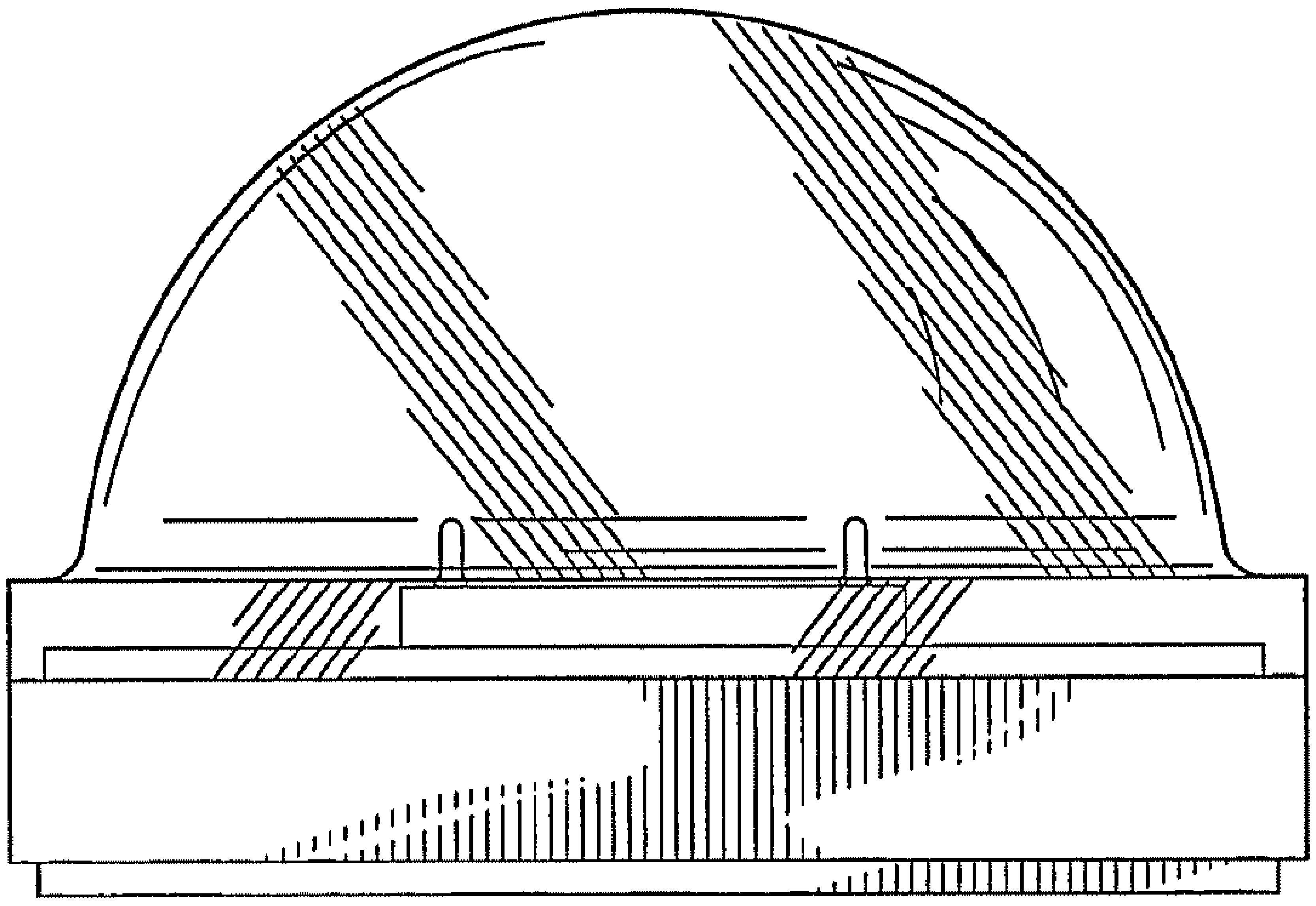


FIG. 5

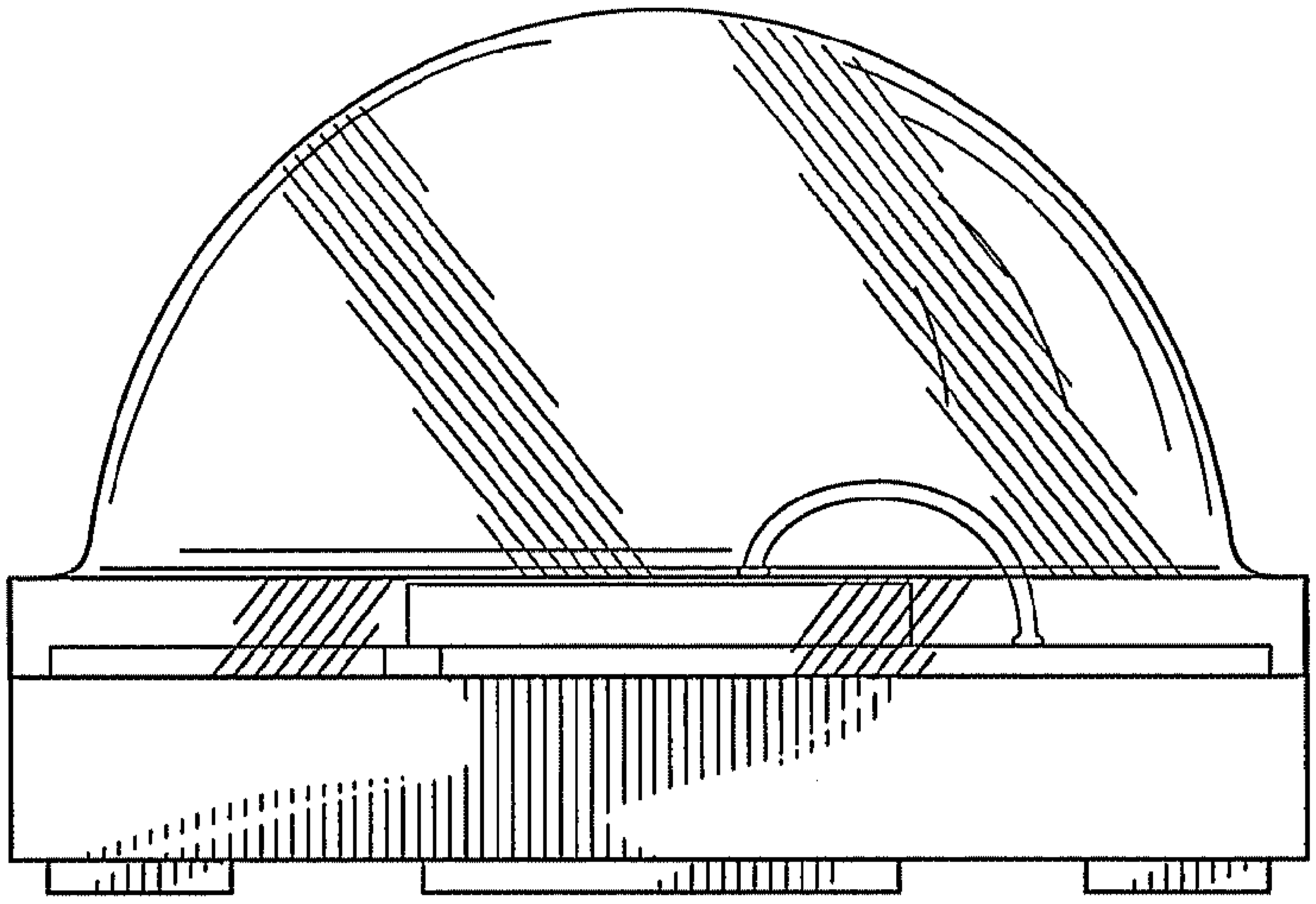


FIG. 6

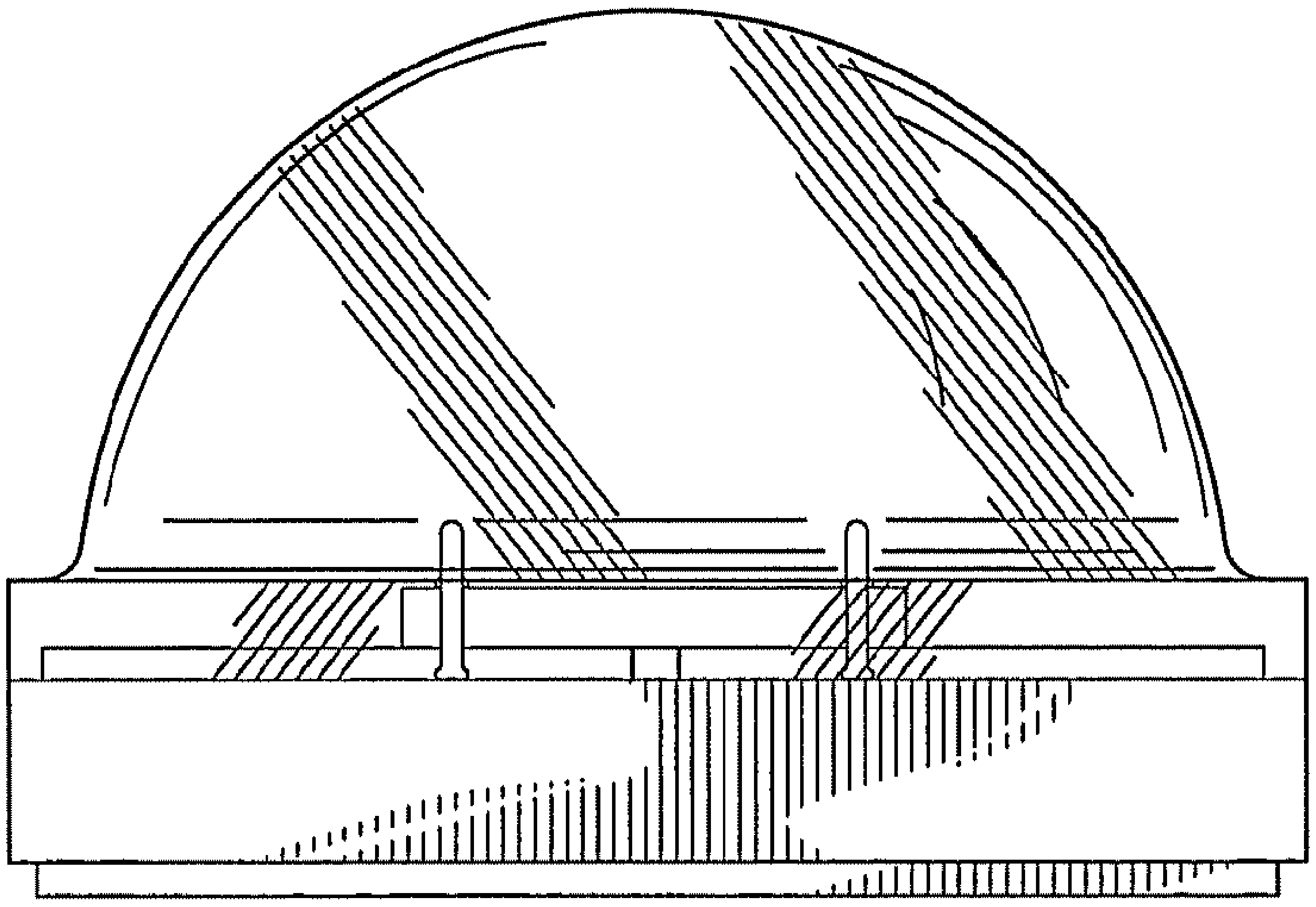
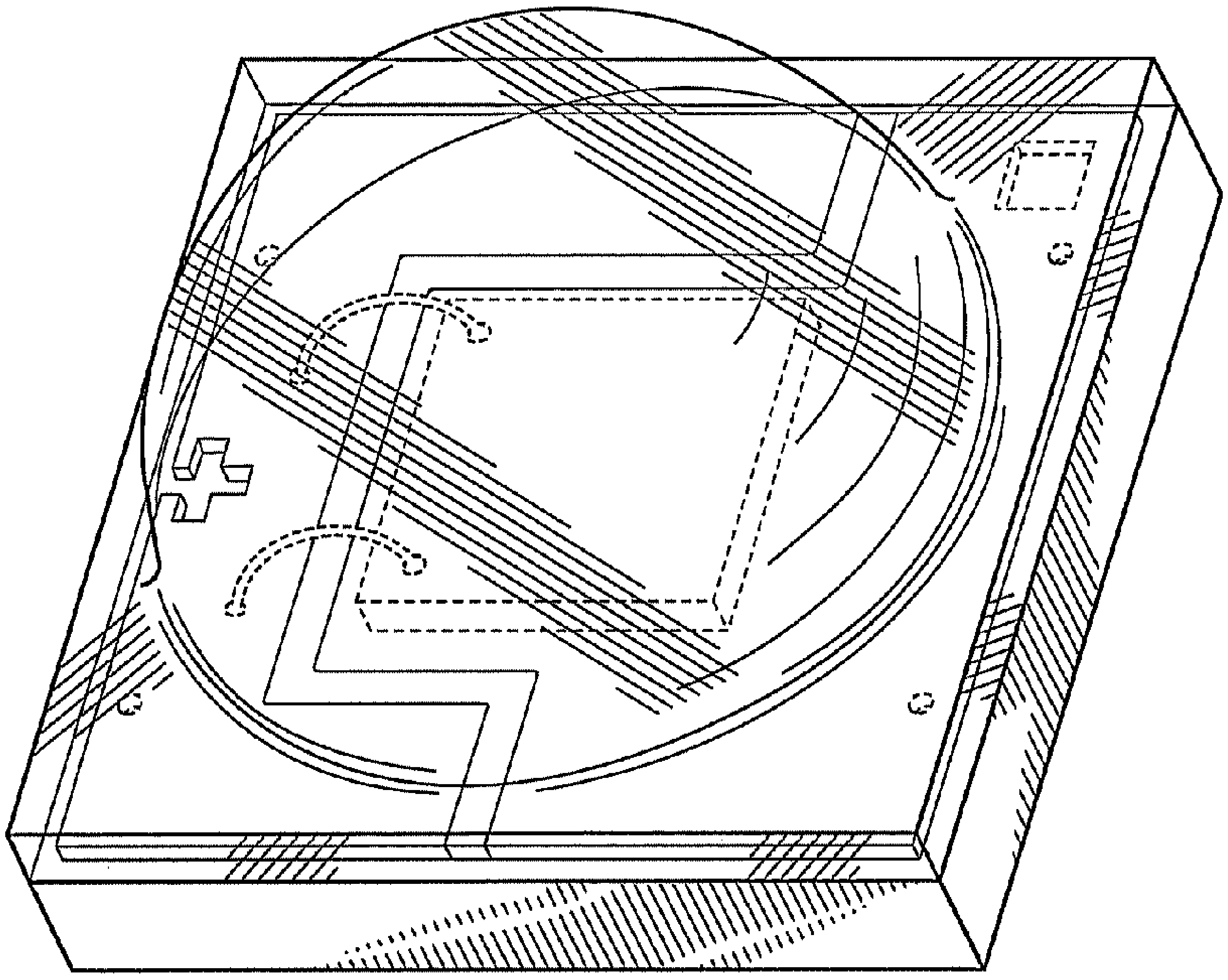


FIG. 7



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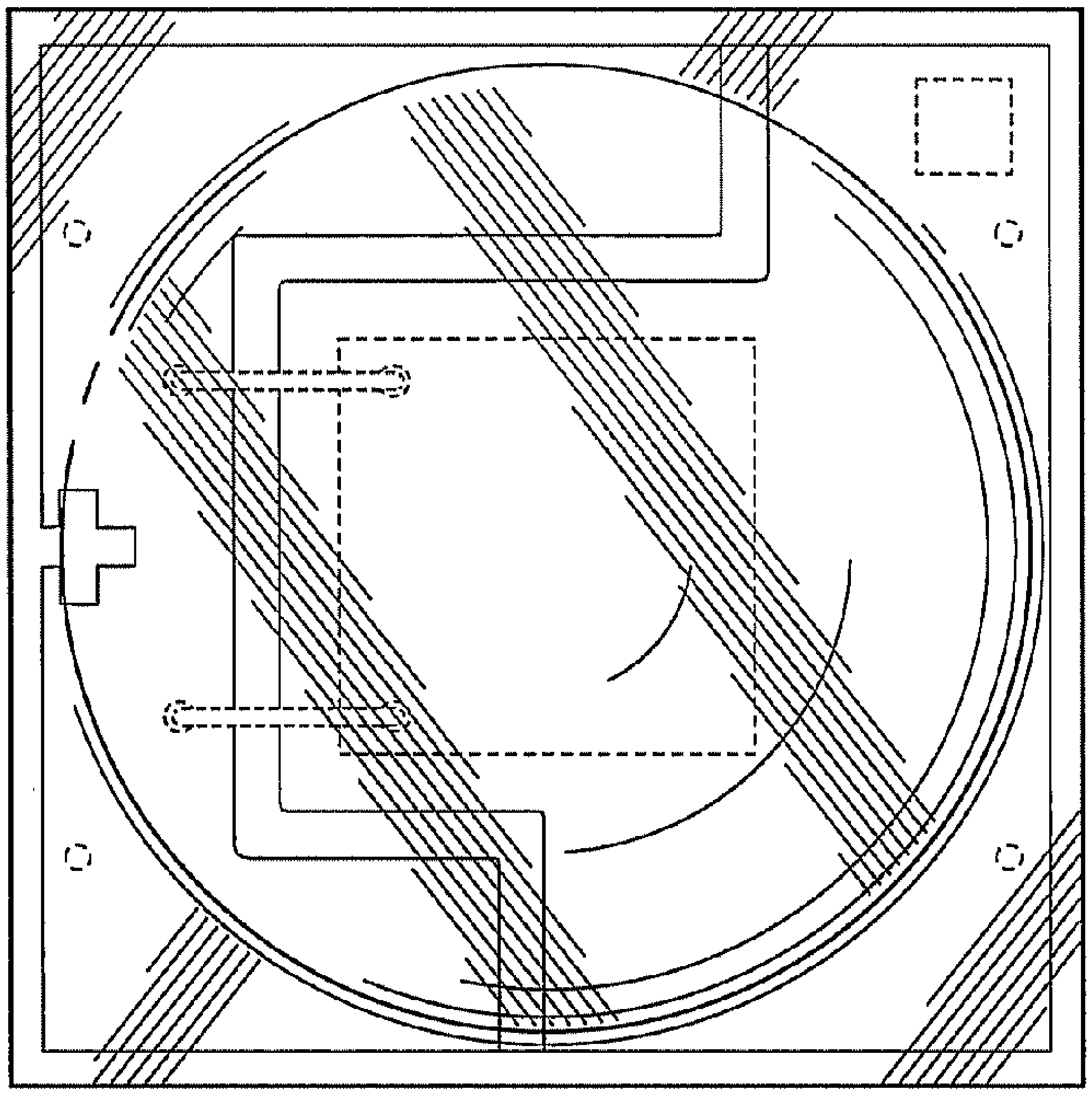


FIG. 9

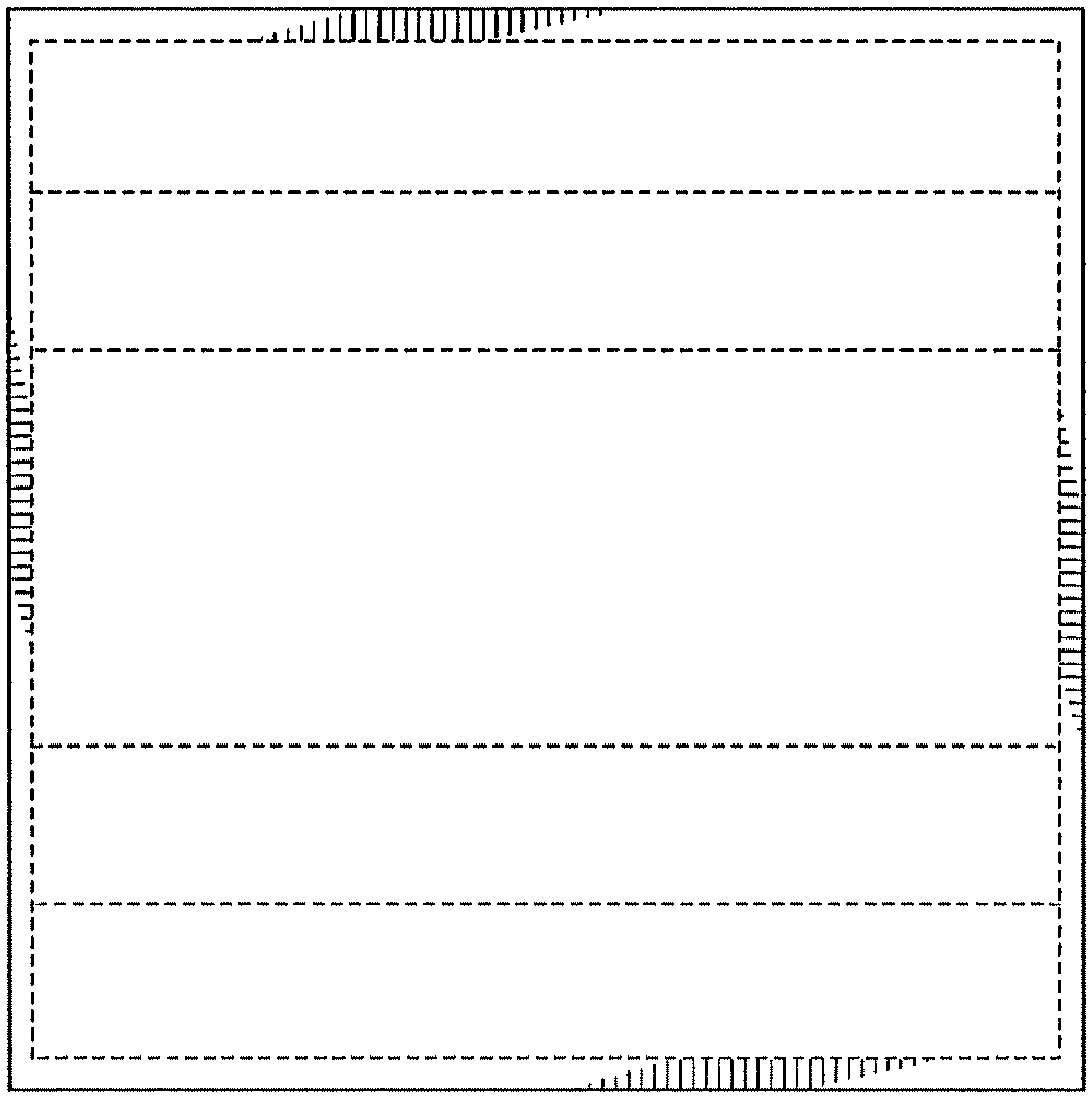


FIG. 10

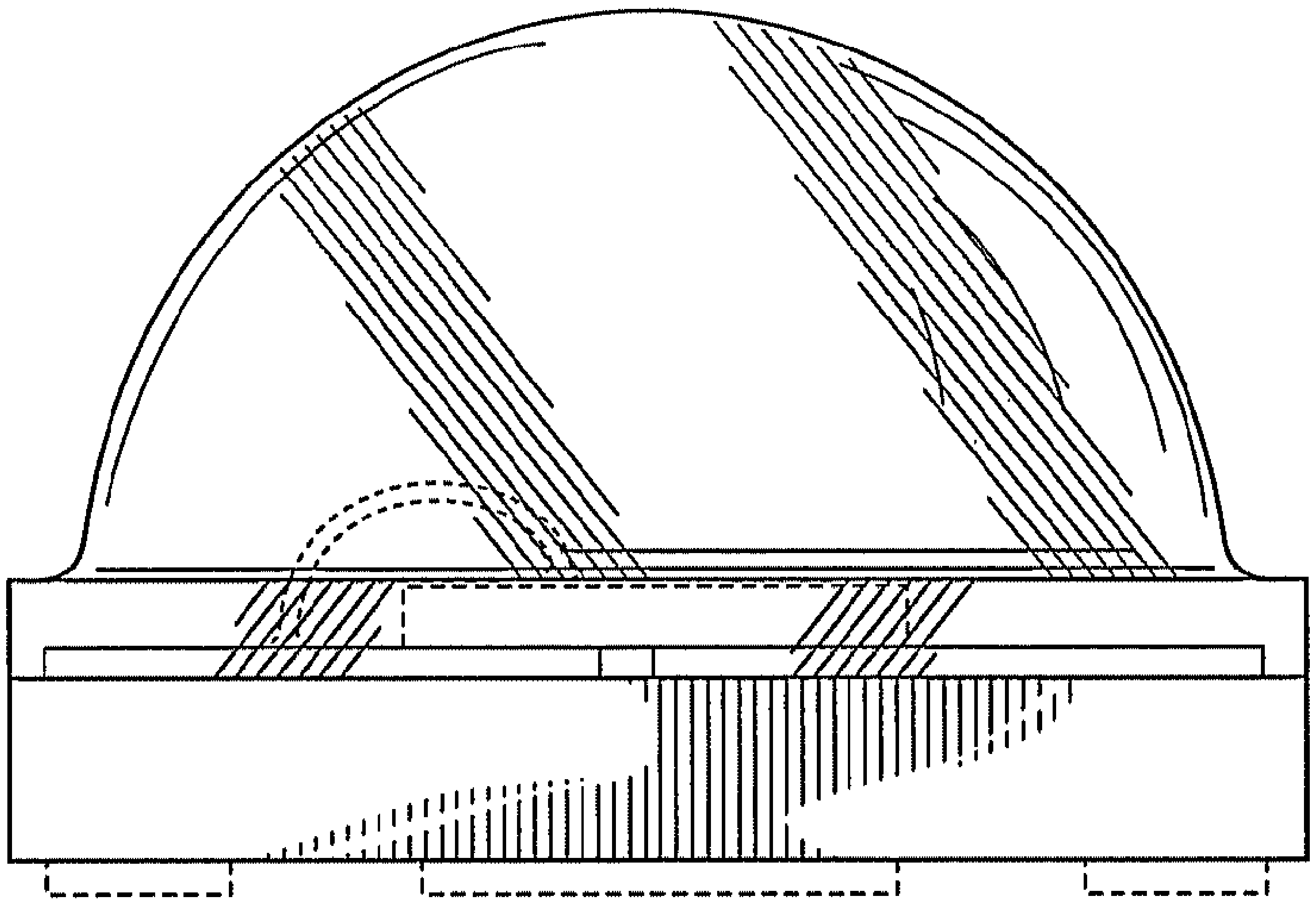


FIG. 11

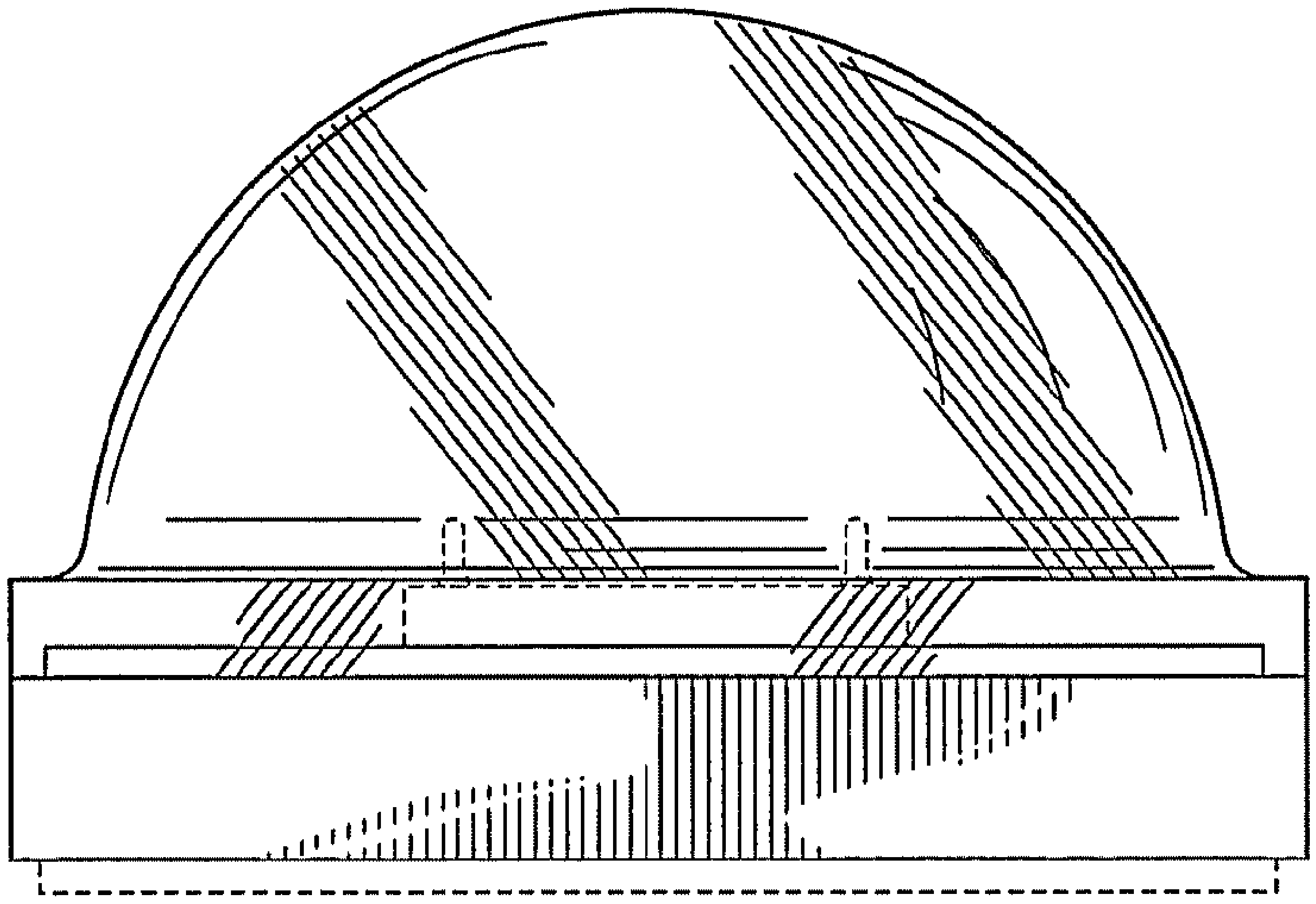
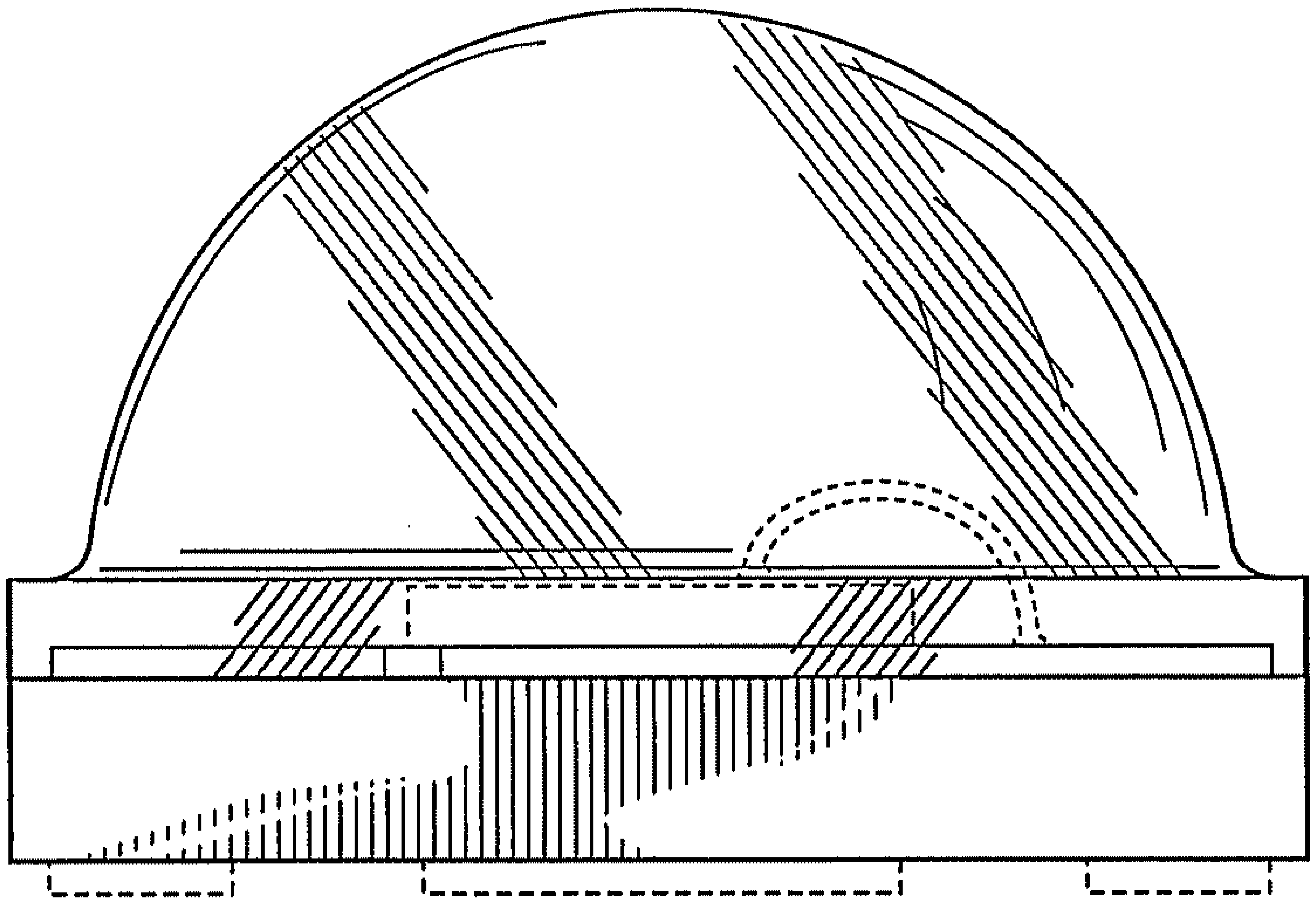


FIG. 12



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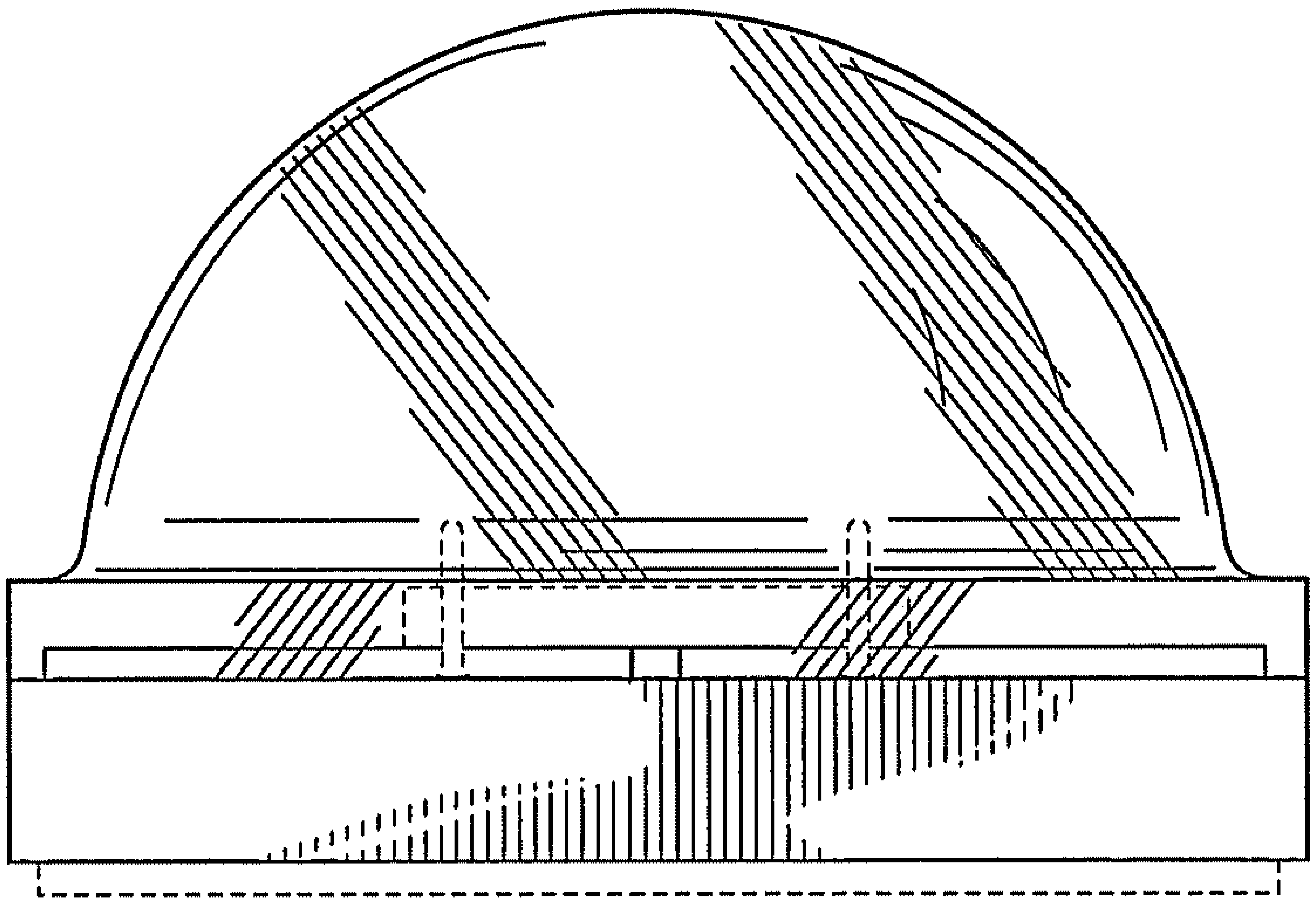

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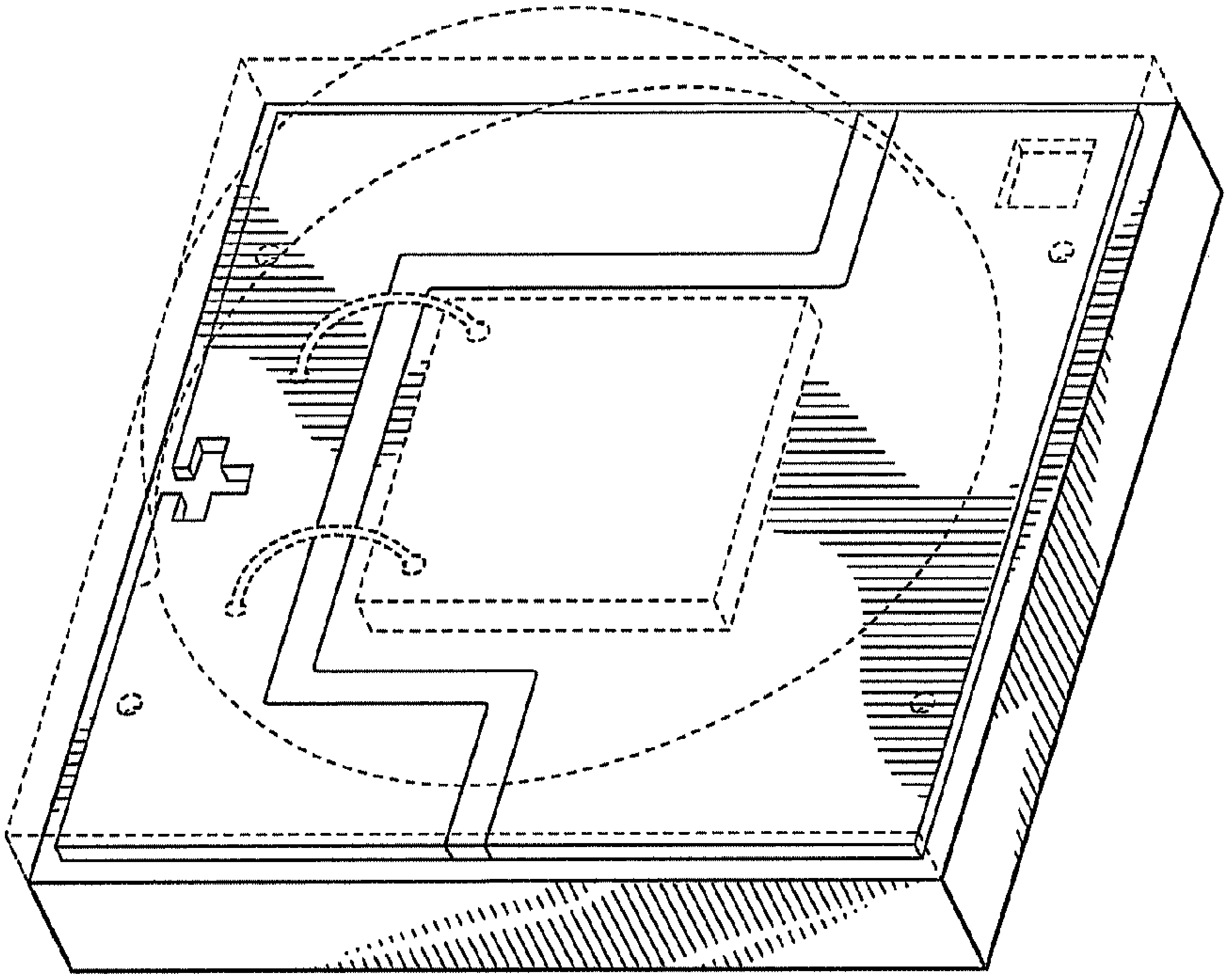

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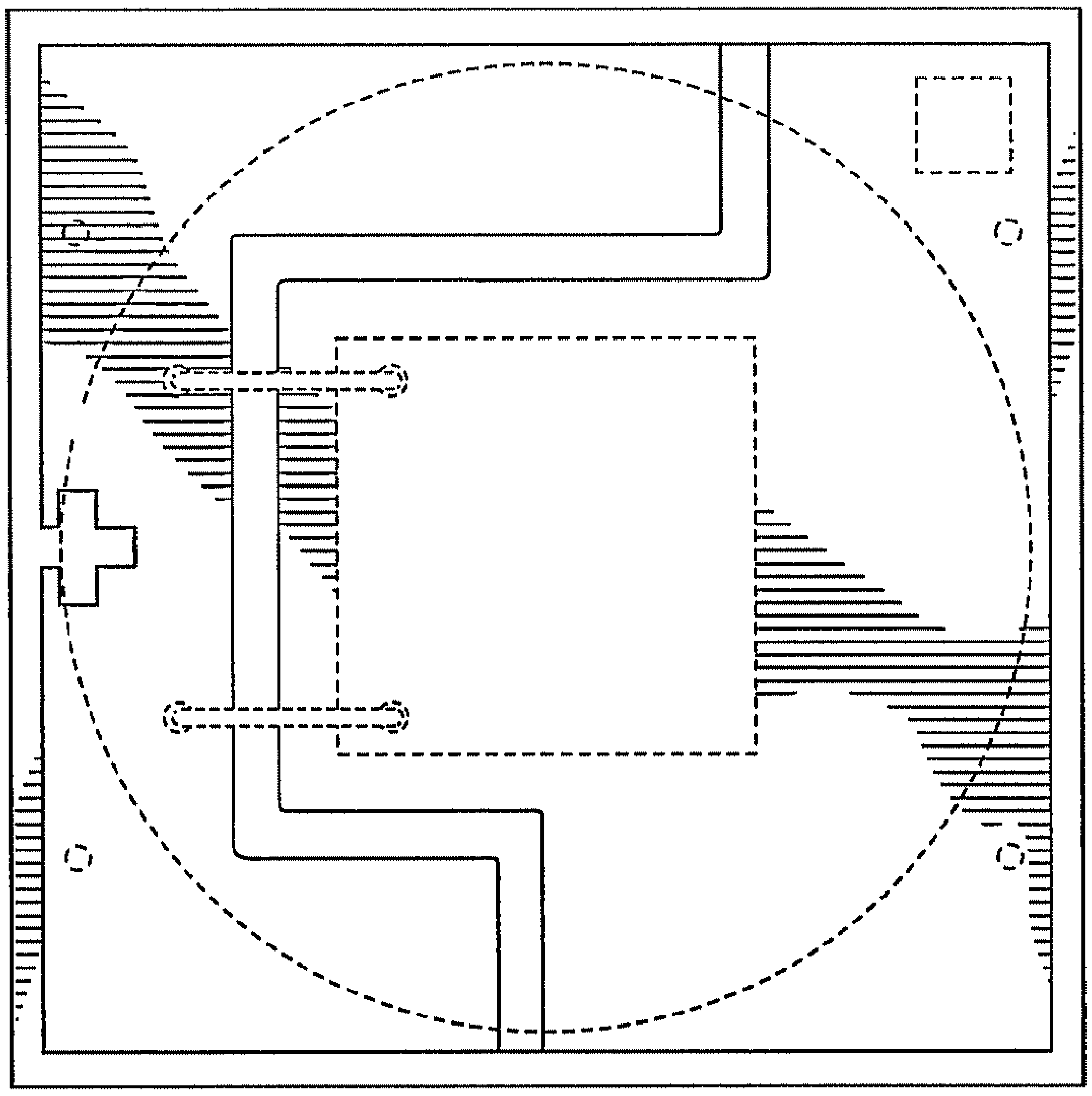

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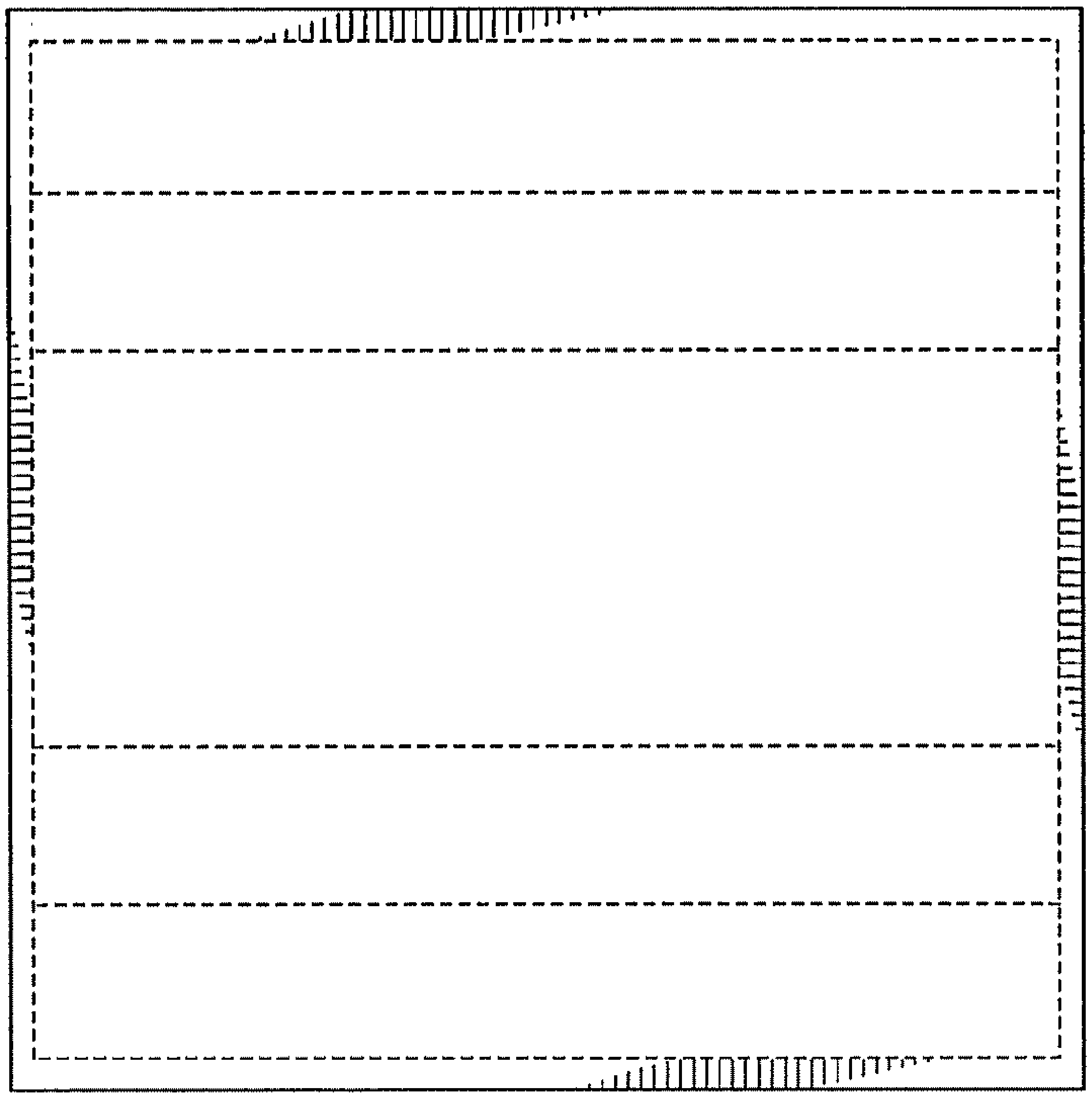

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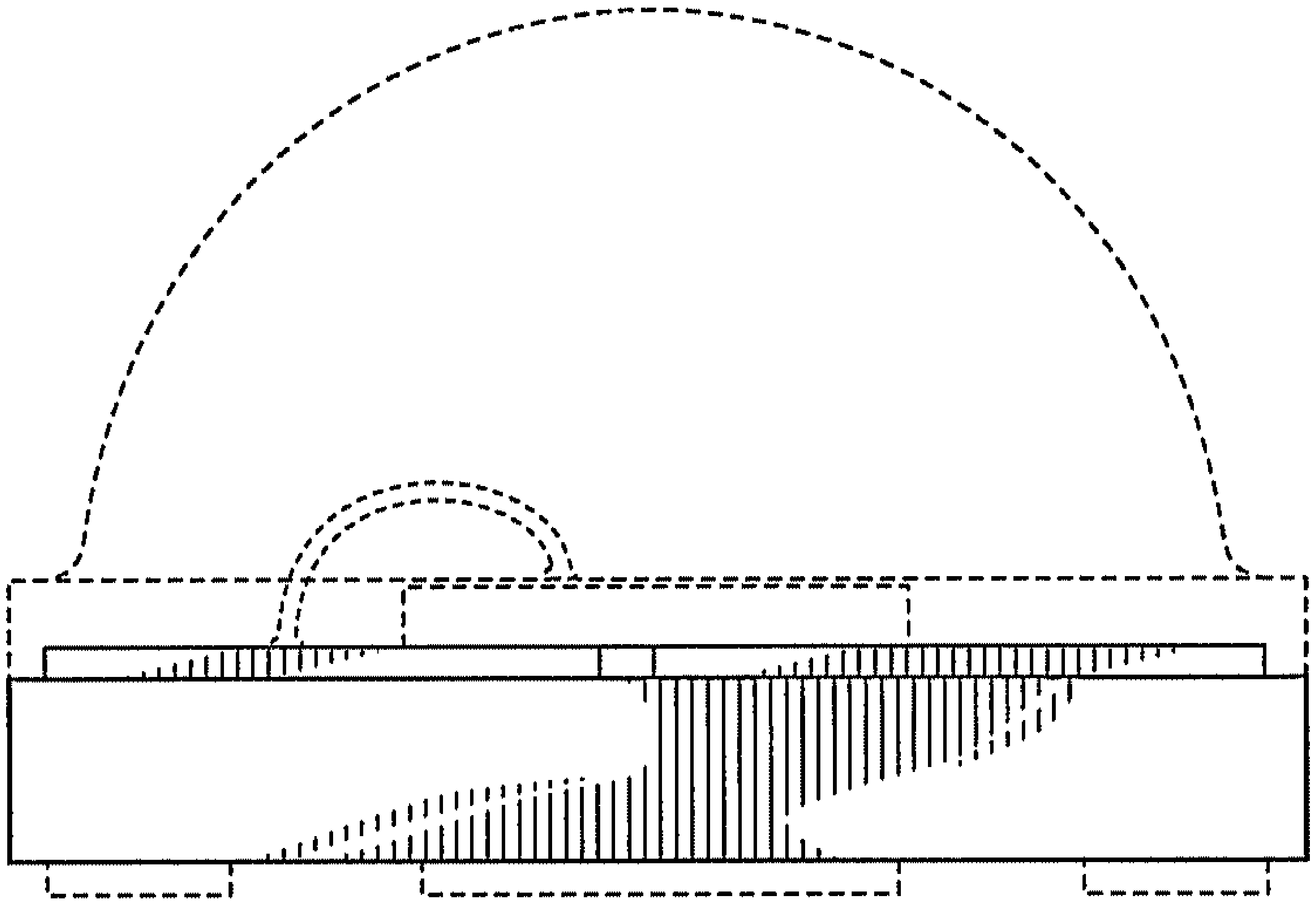

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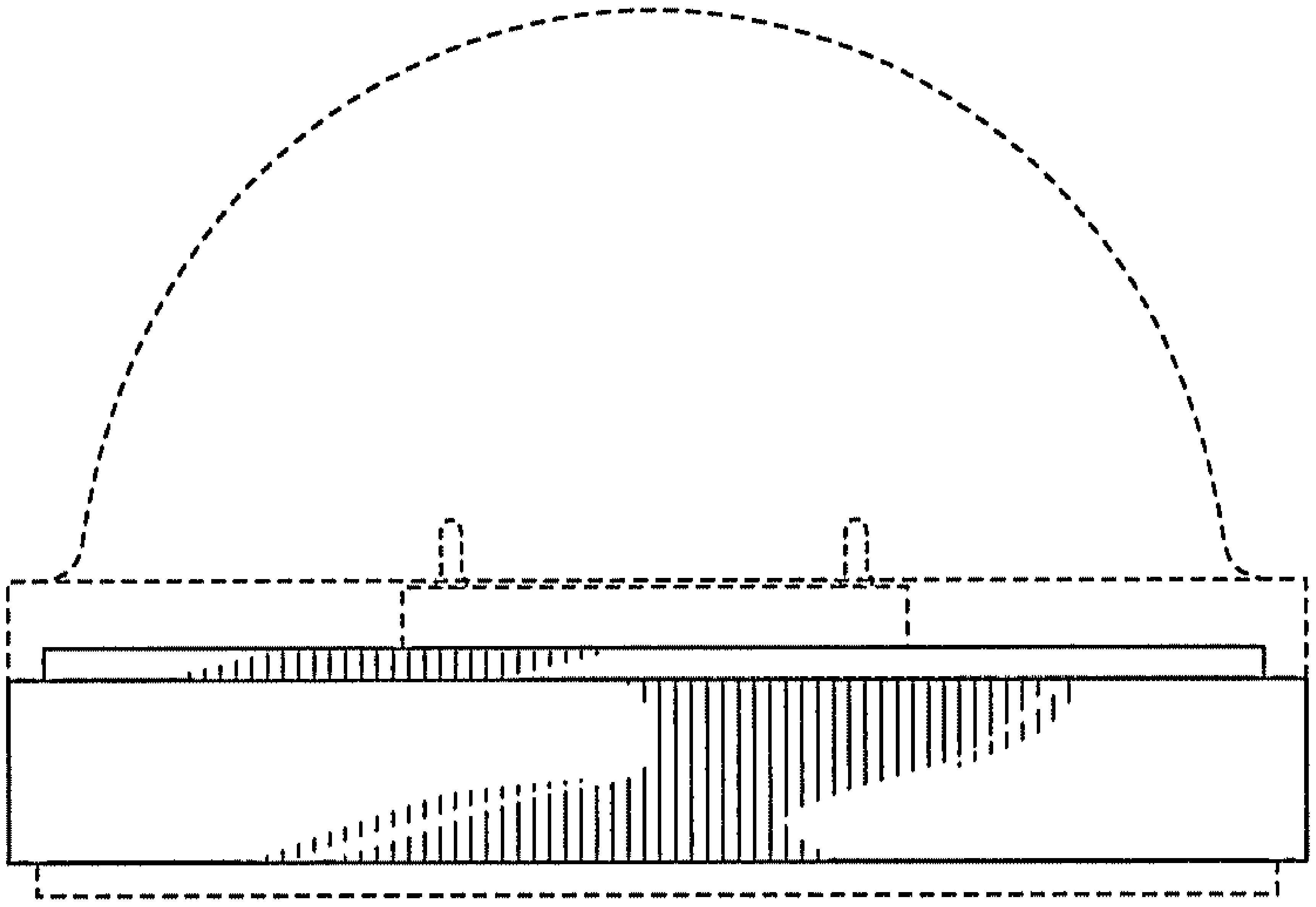

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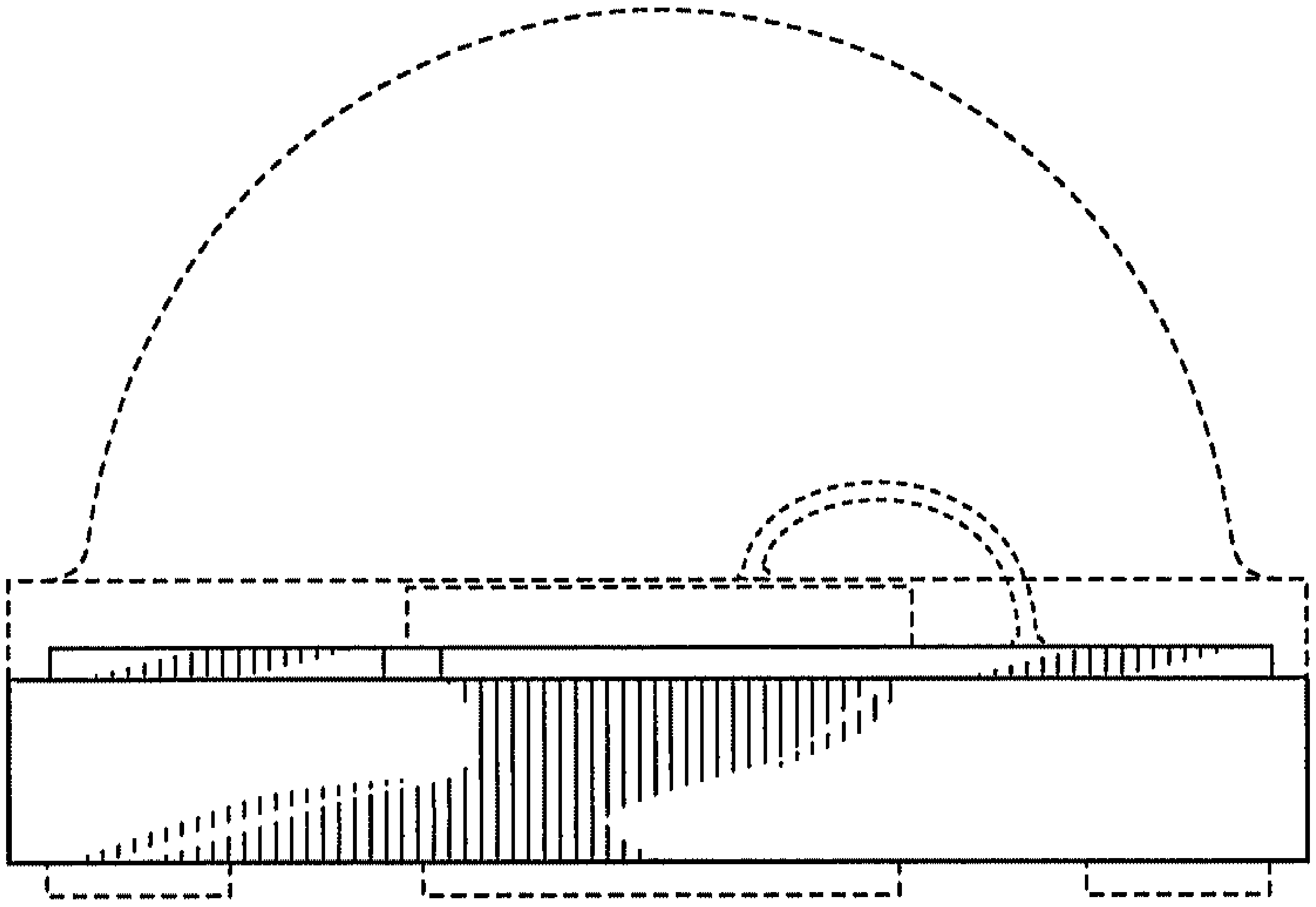

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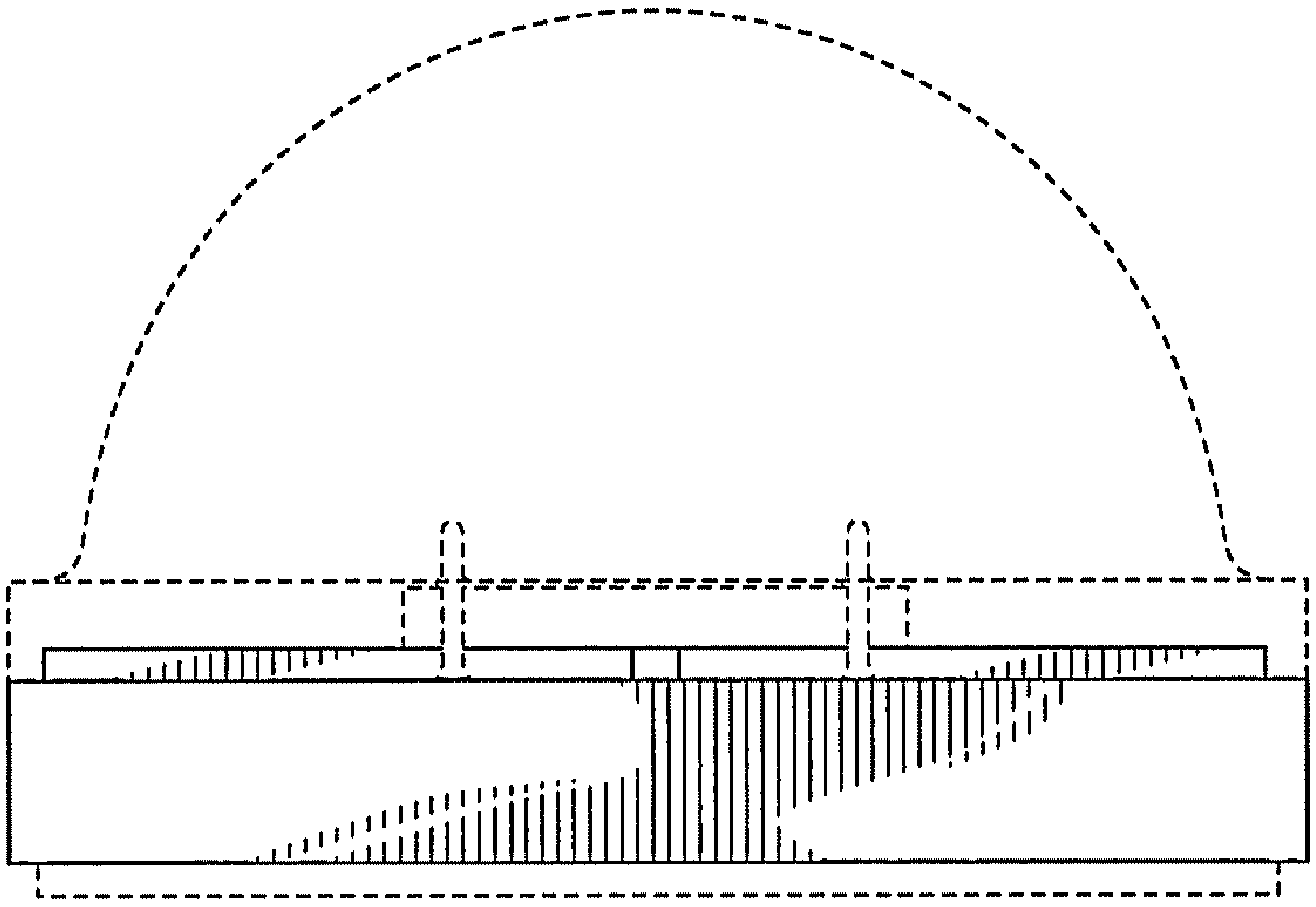

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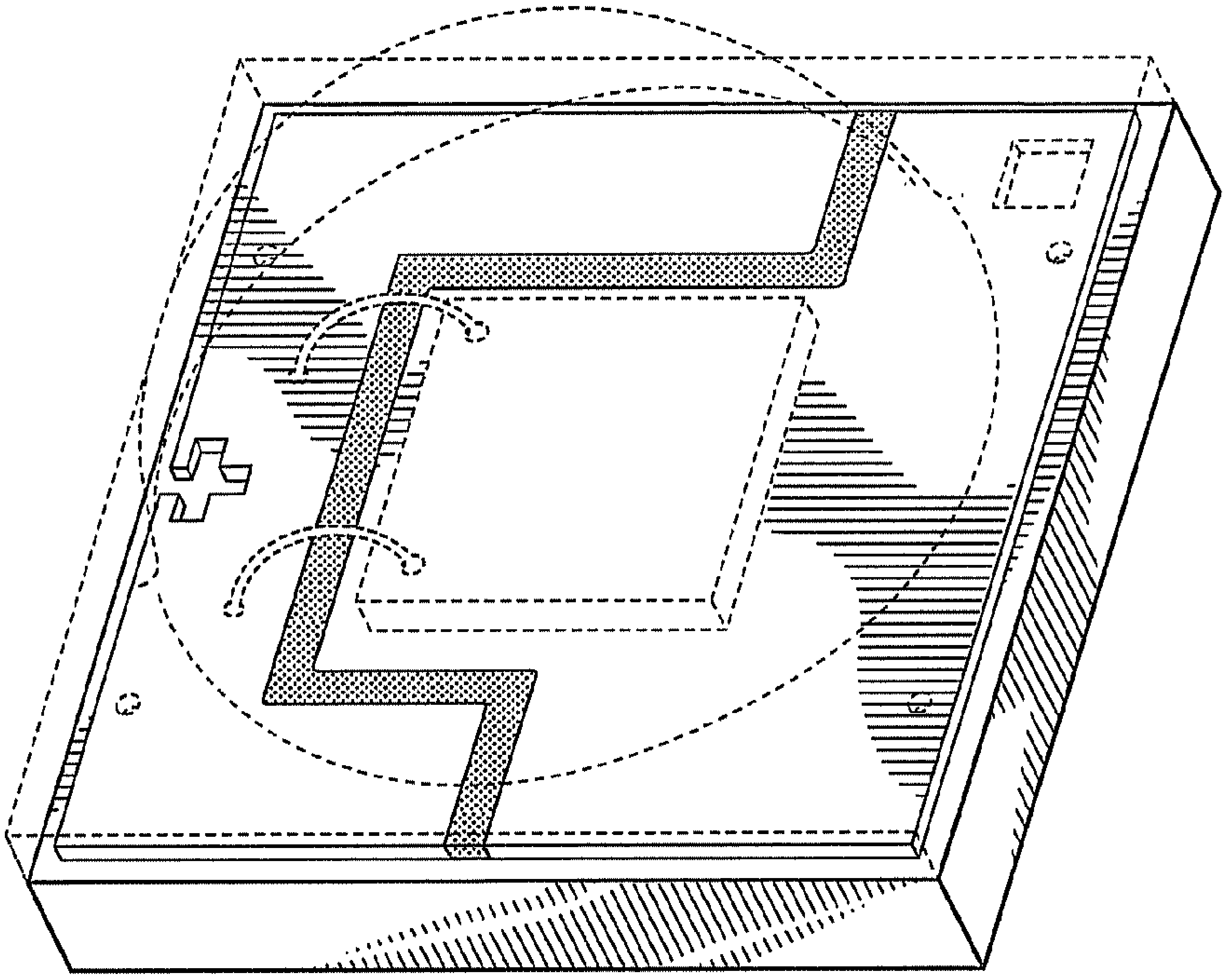

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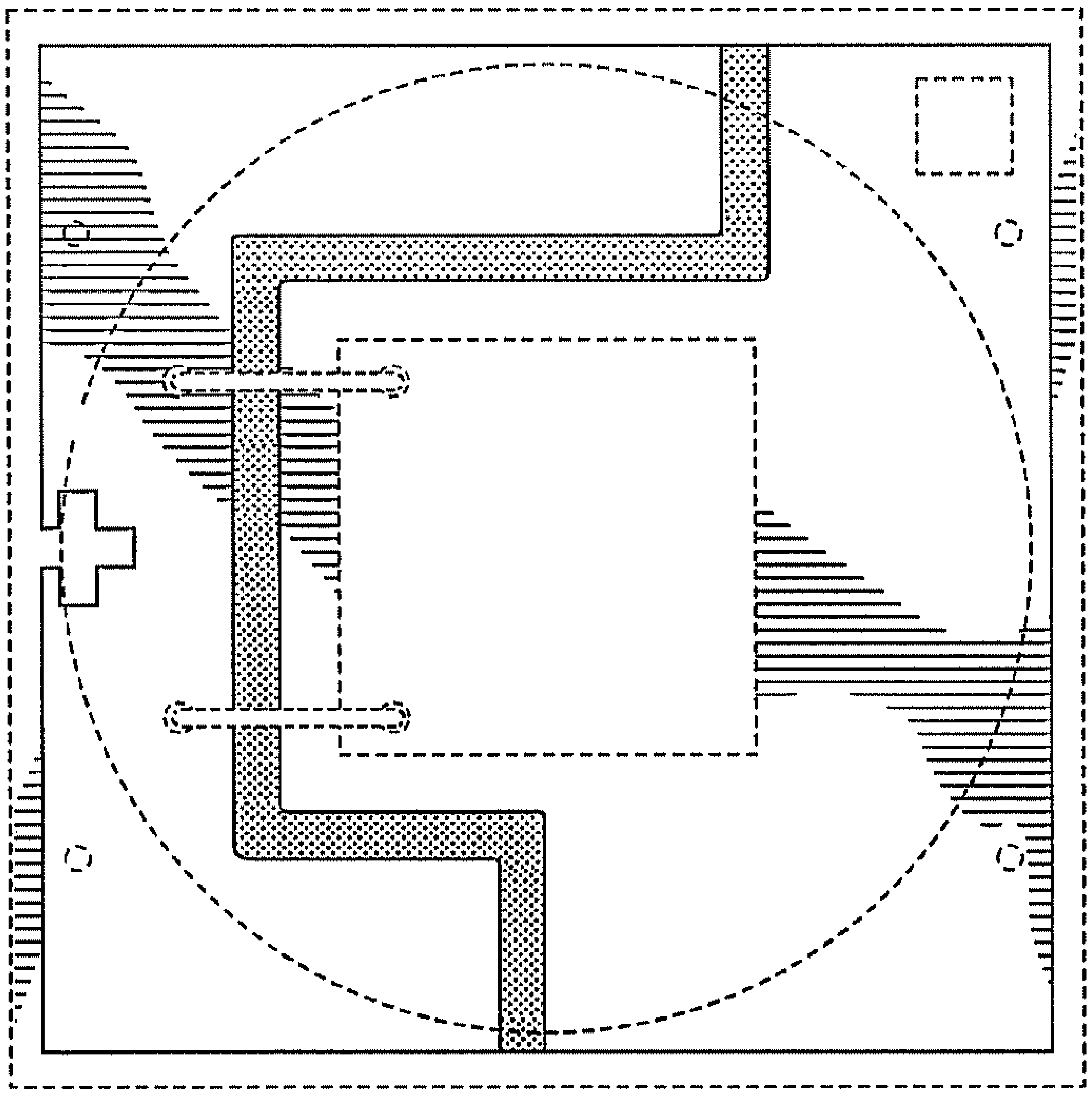

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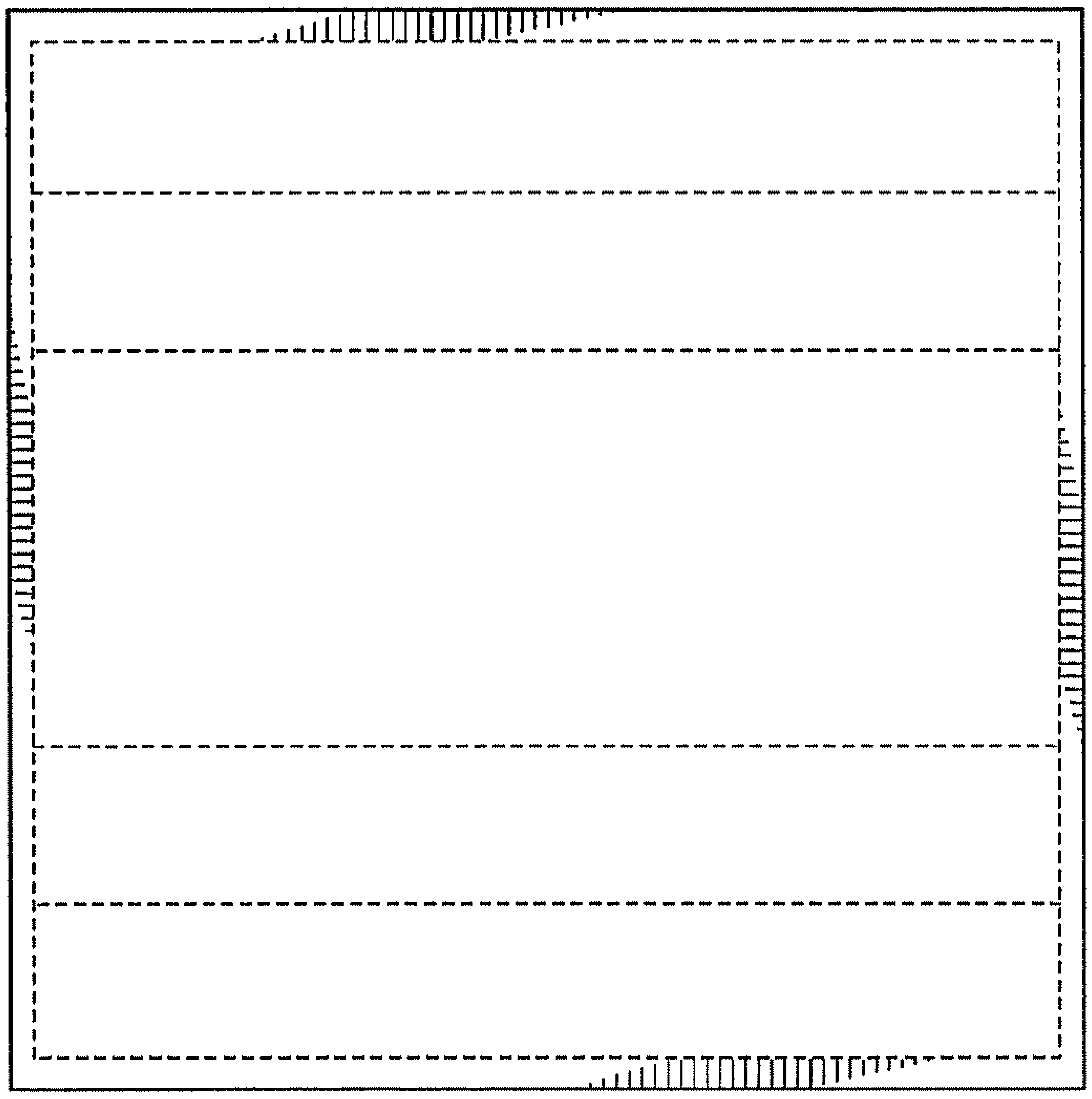

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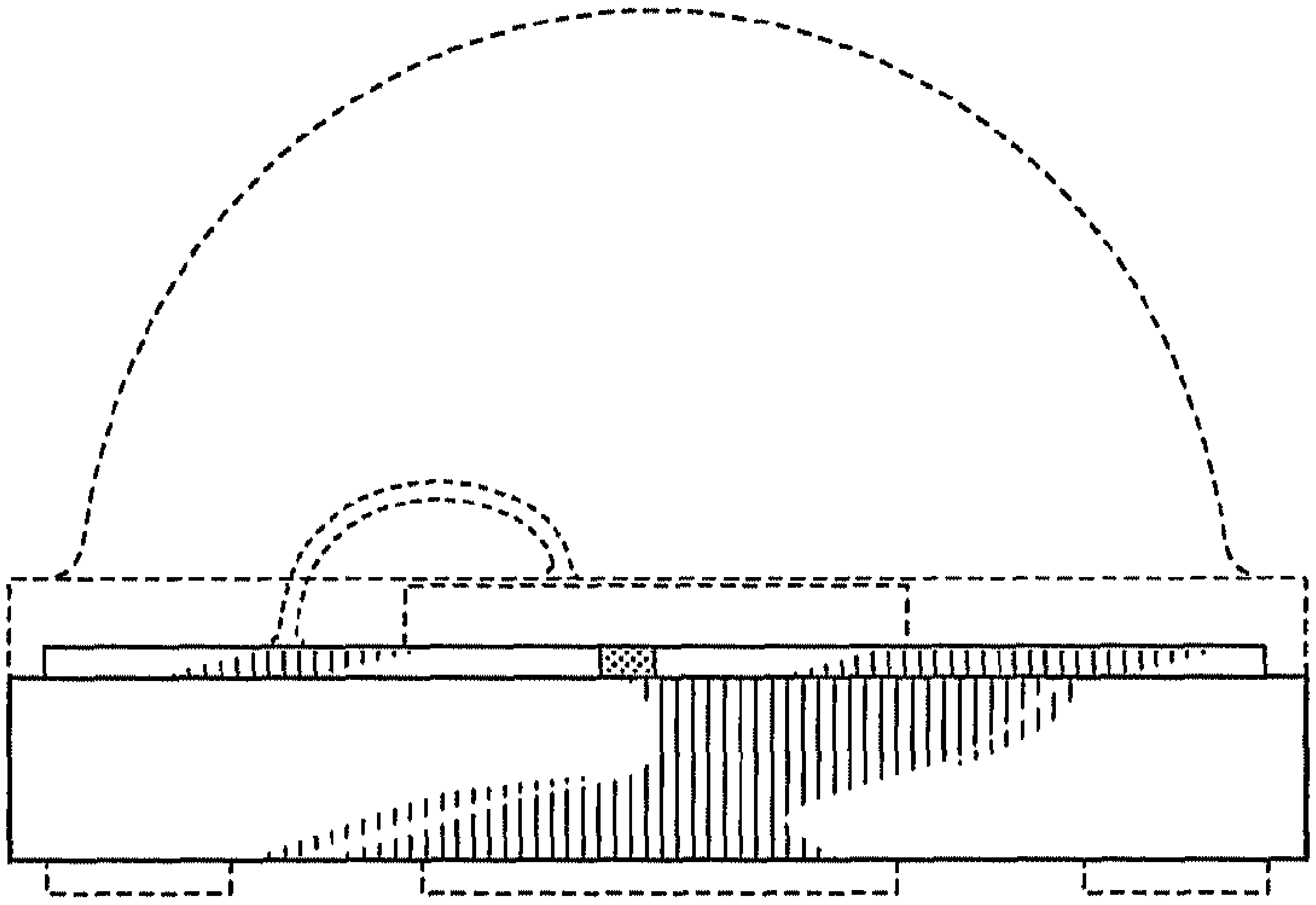


FIG. 25

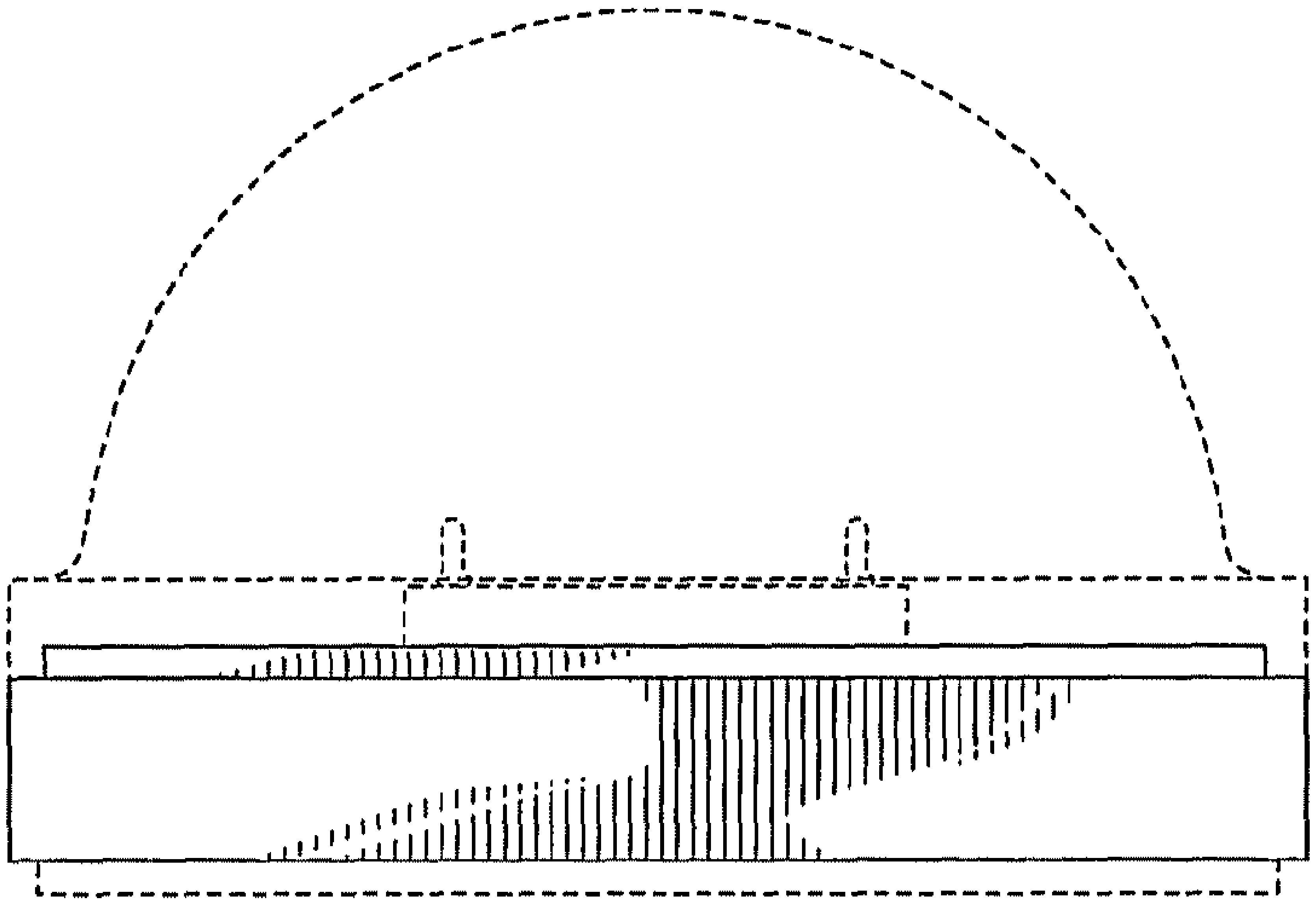
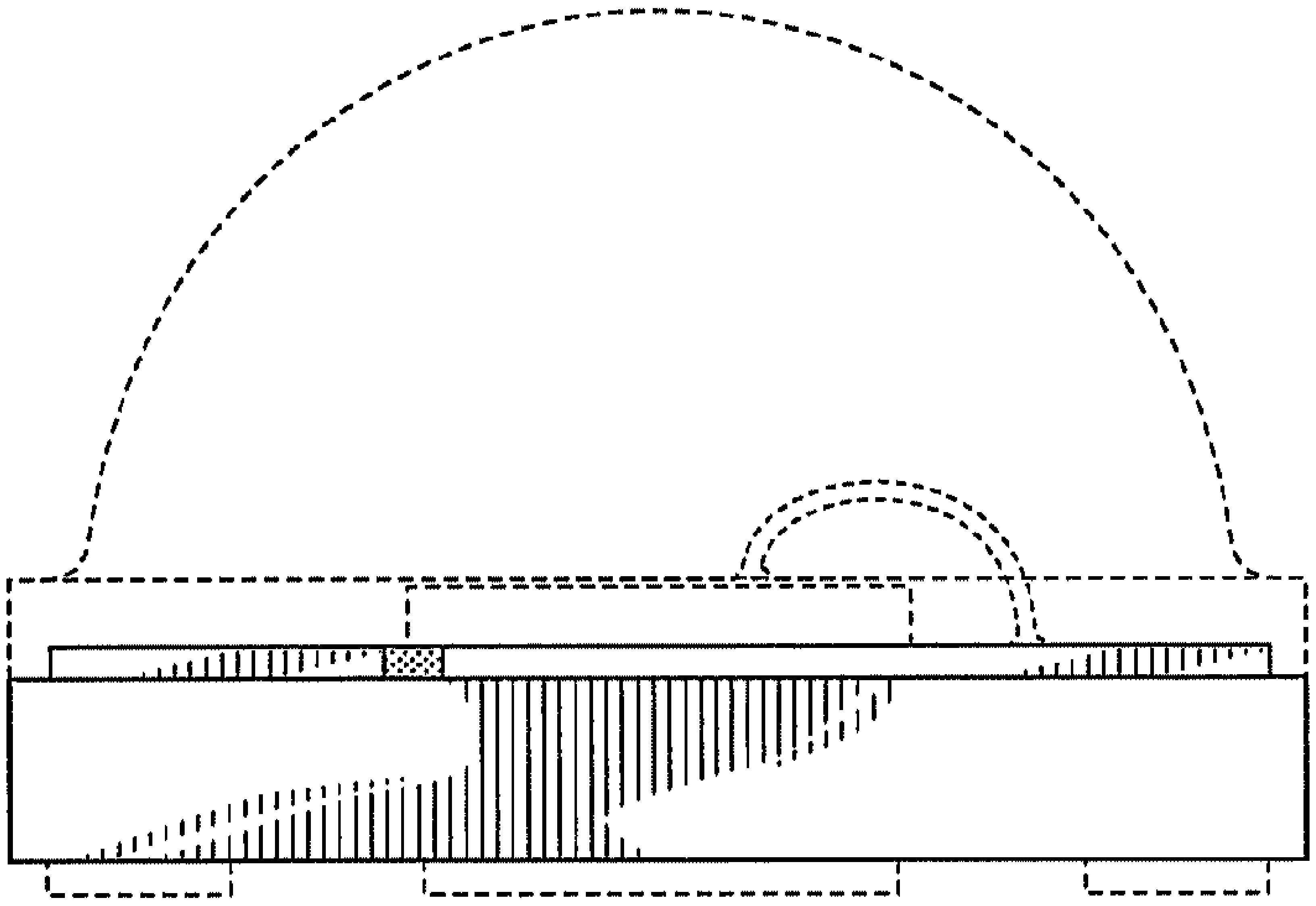


FIG. 26



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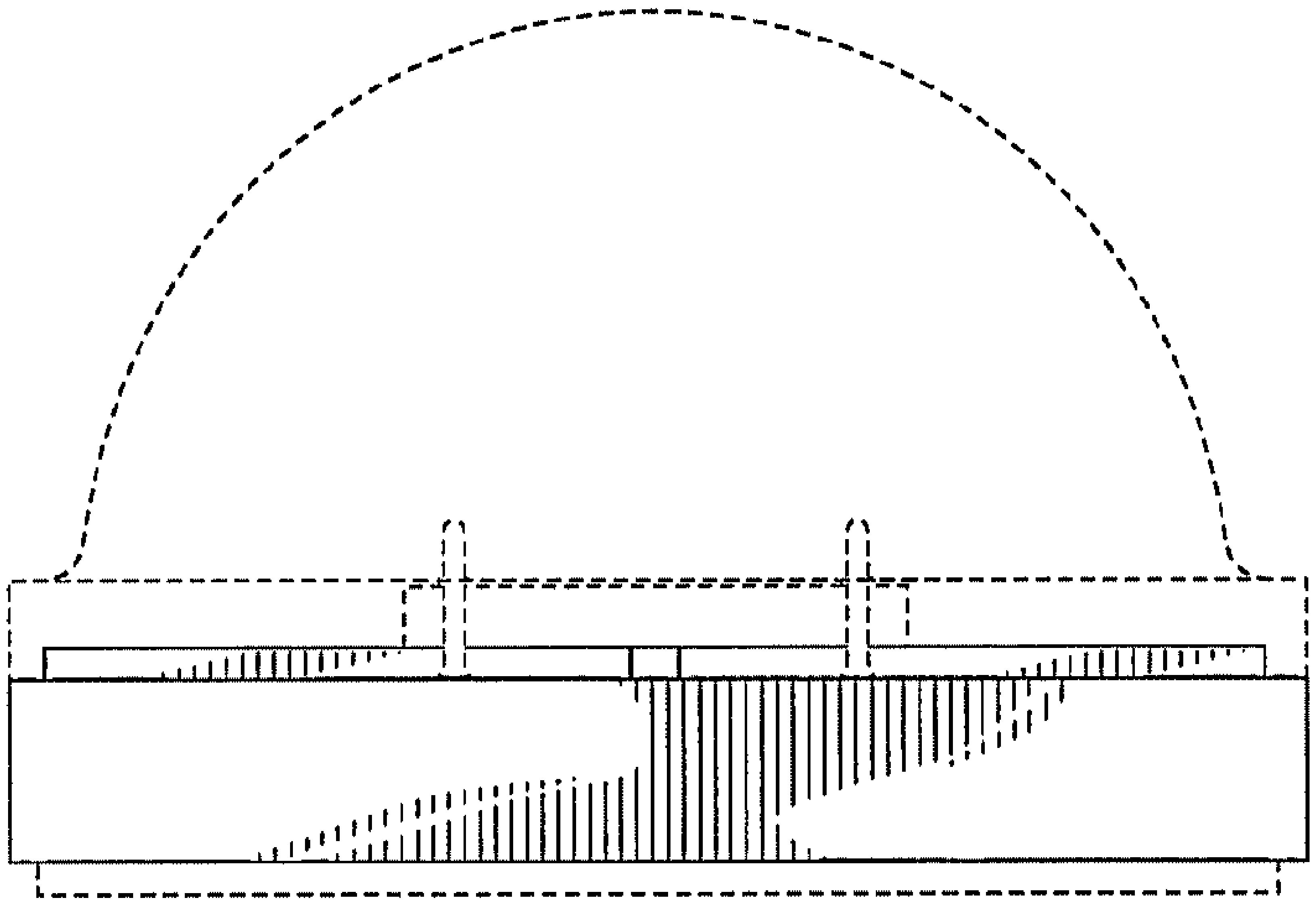

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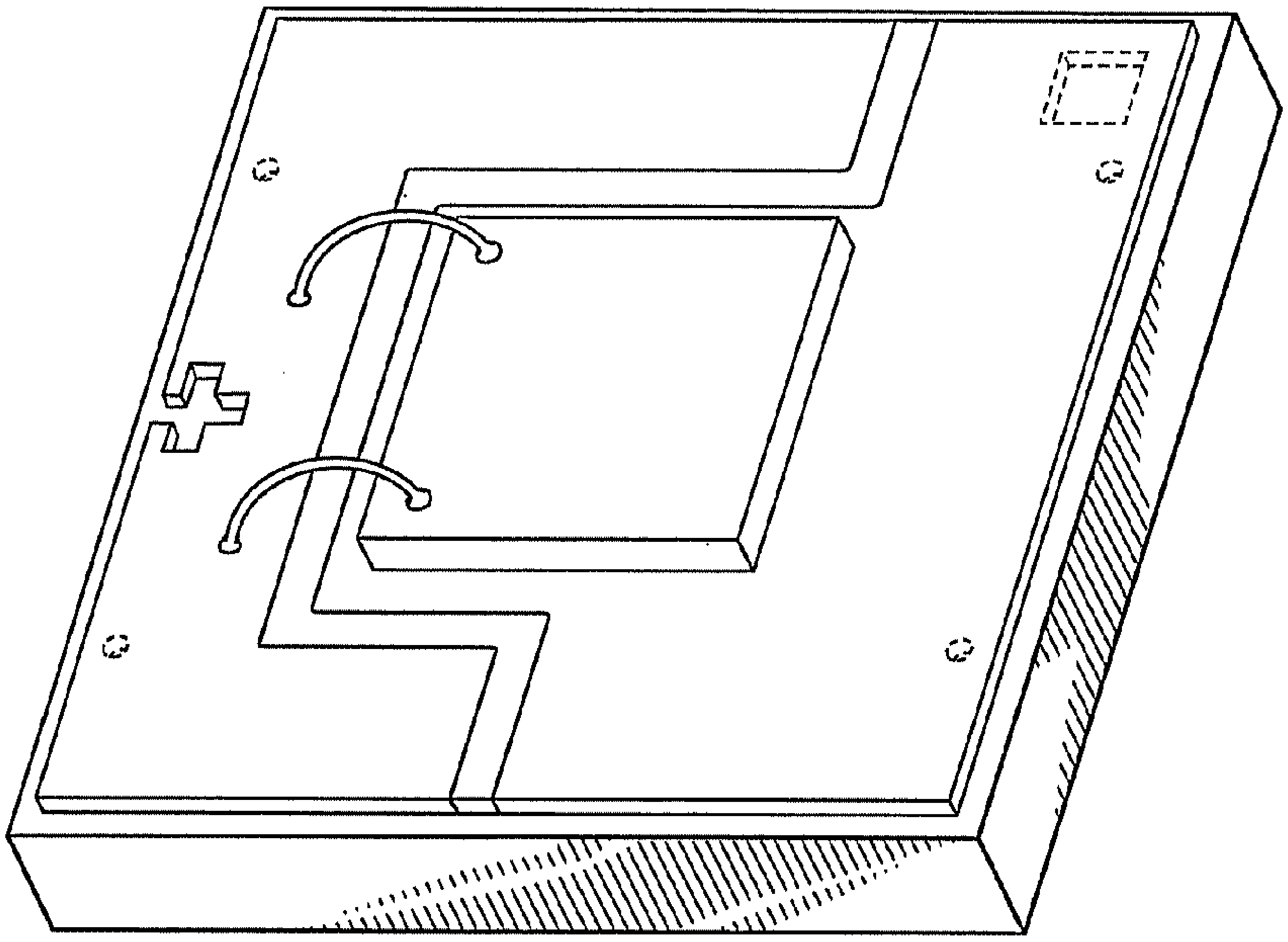


FIG. 29

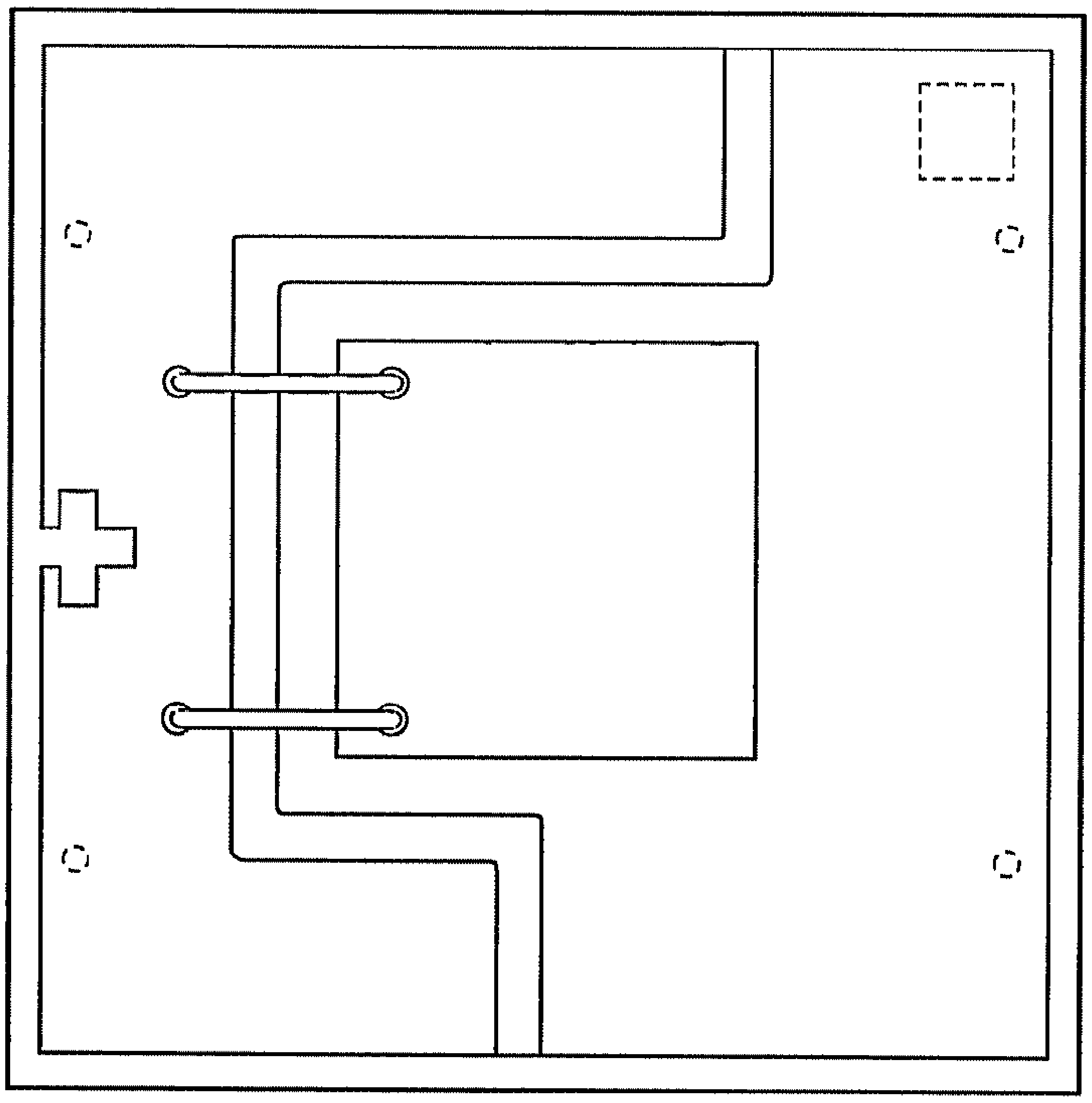
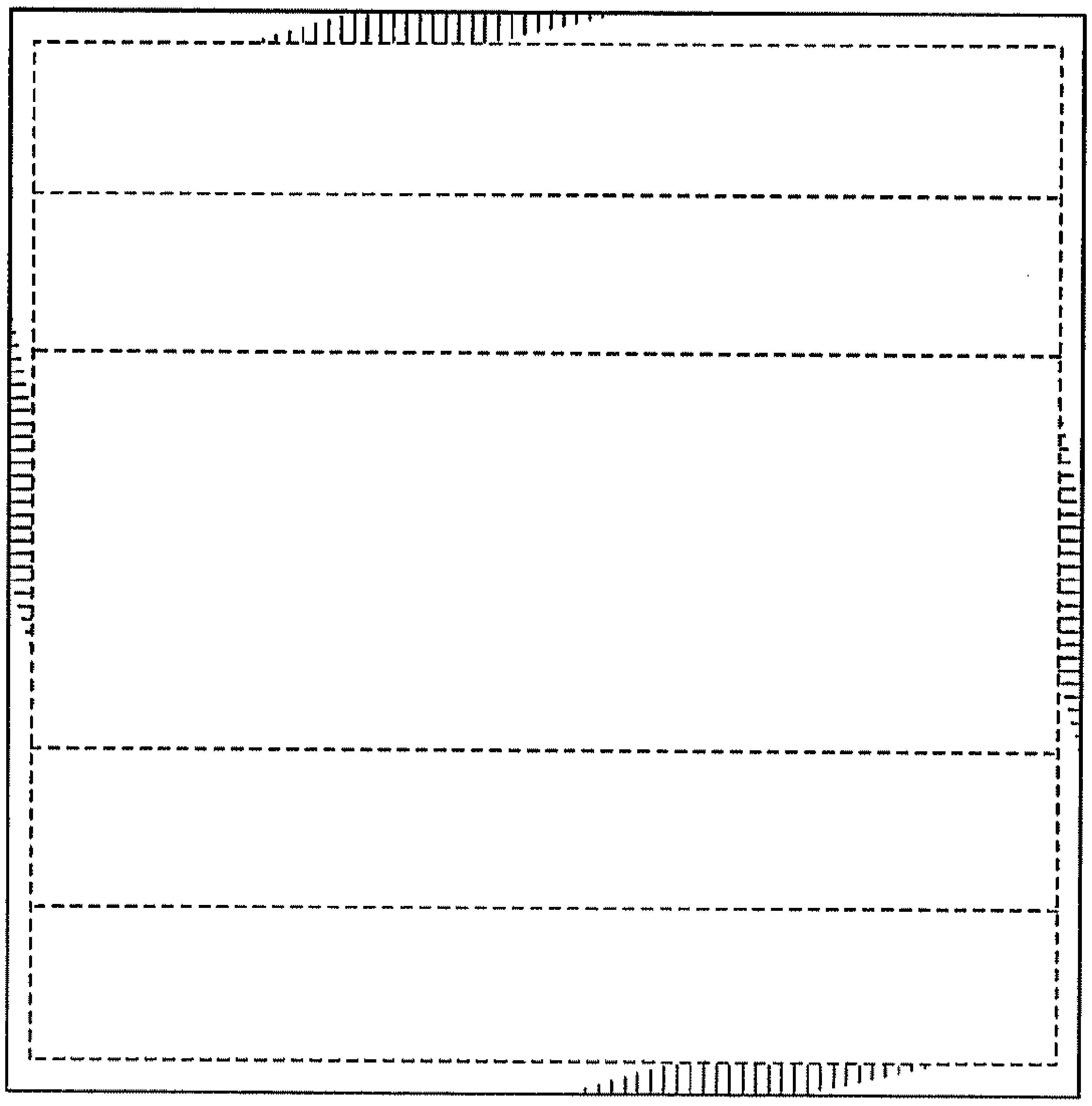


FIG. 30



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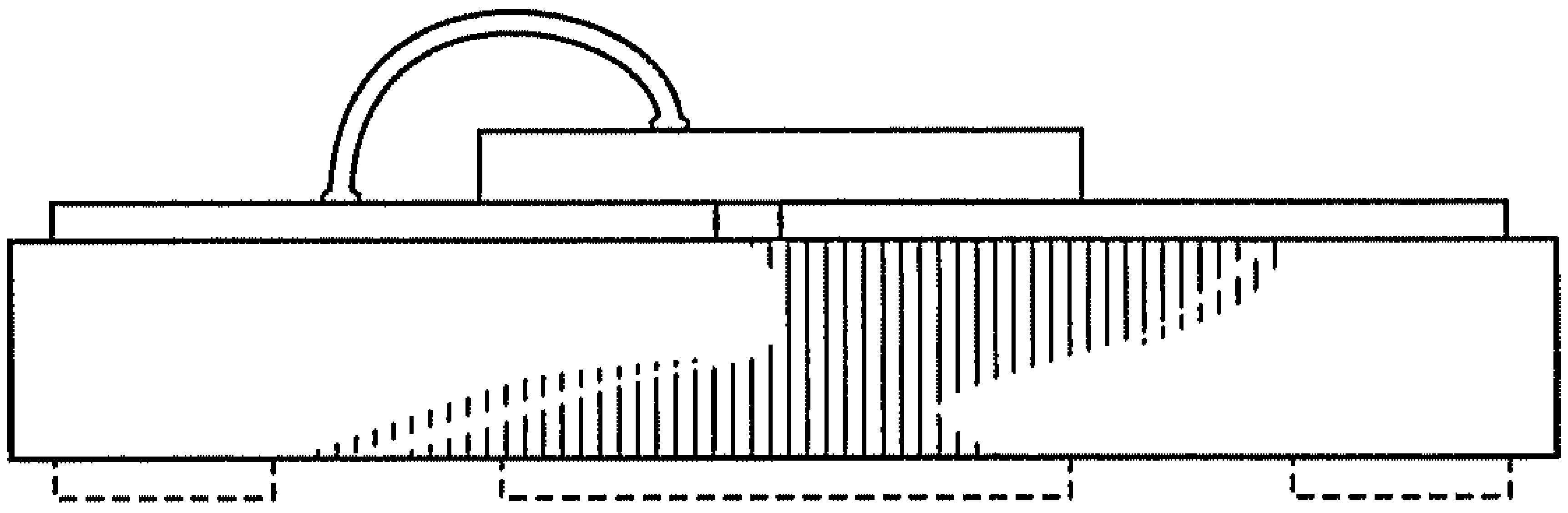

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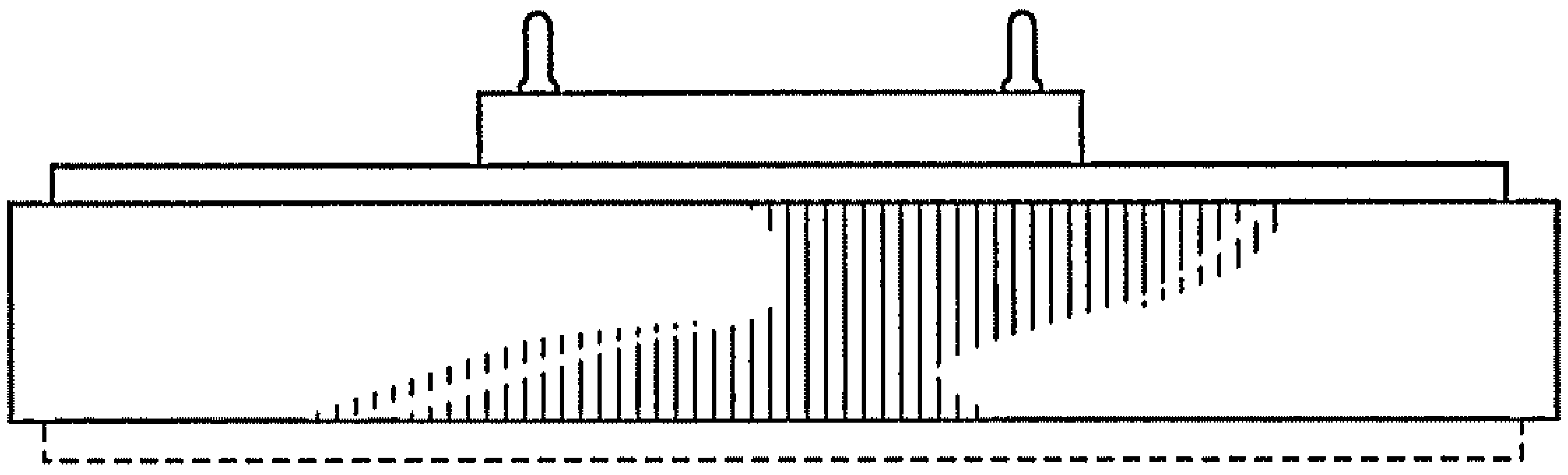


FIG. 33

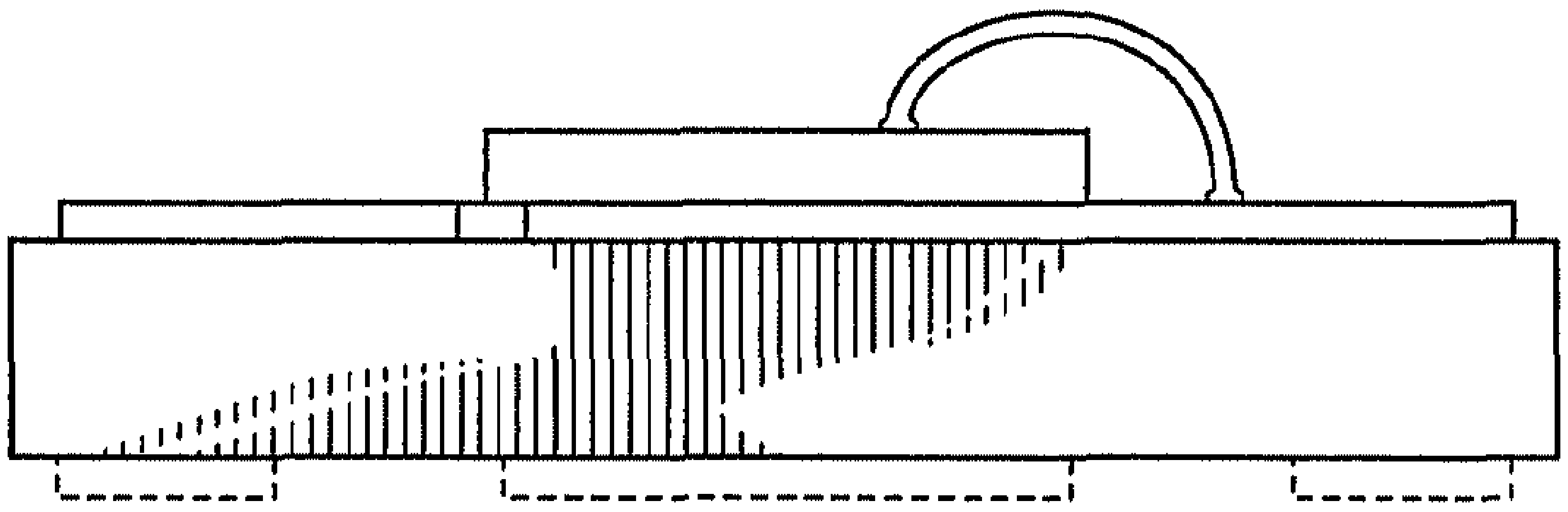


FIG. 34

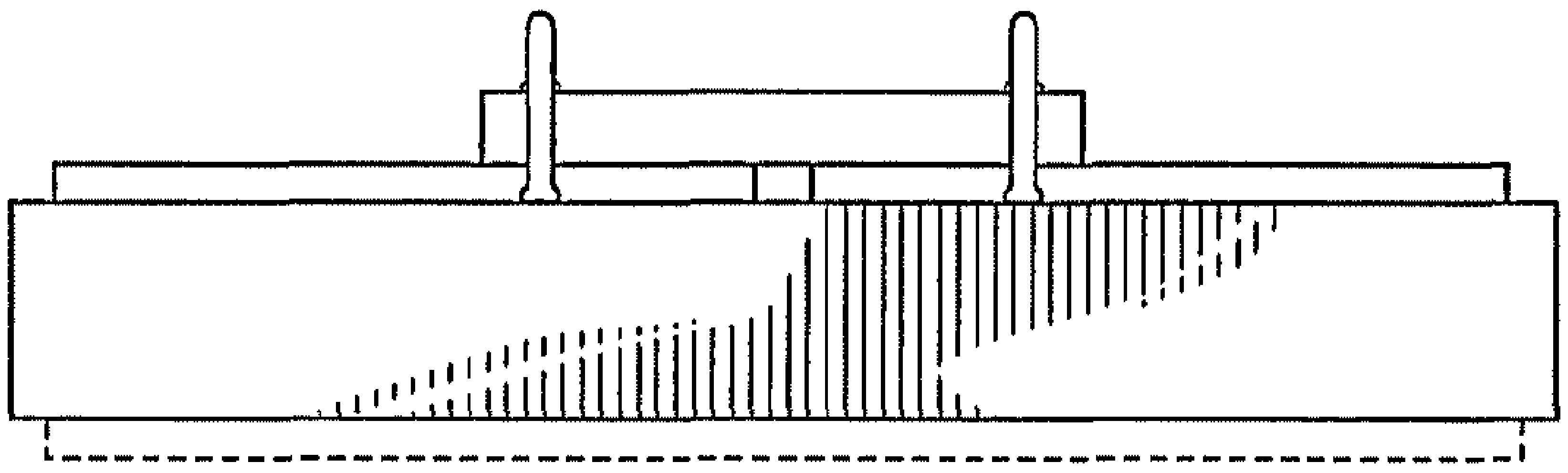


FIG. 35

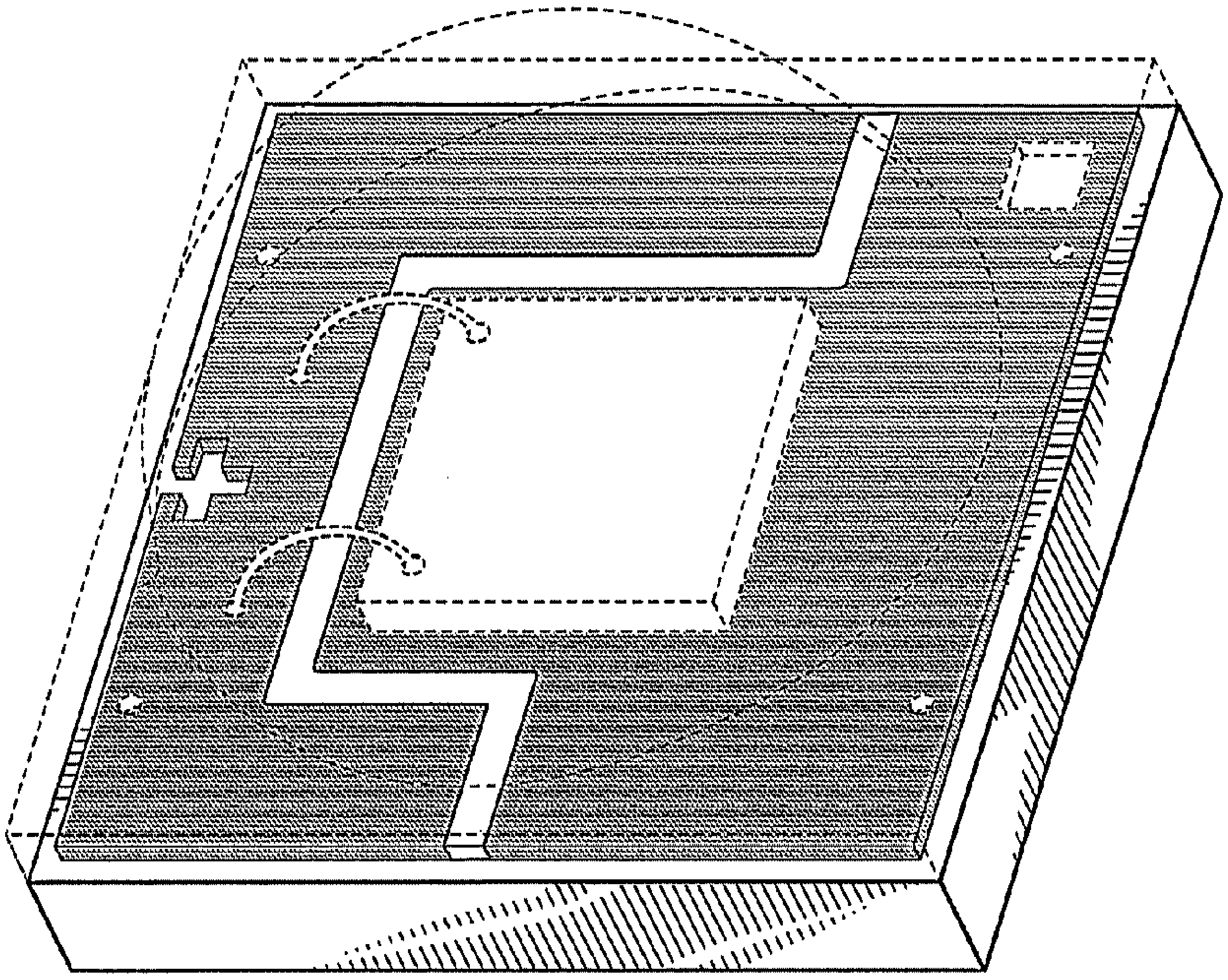


FIG. 36

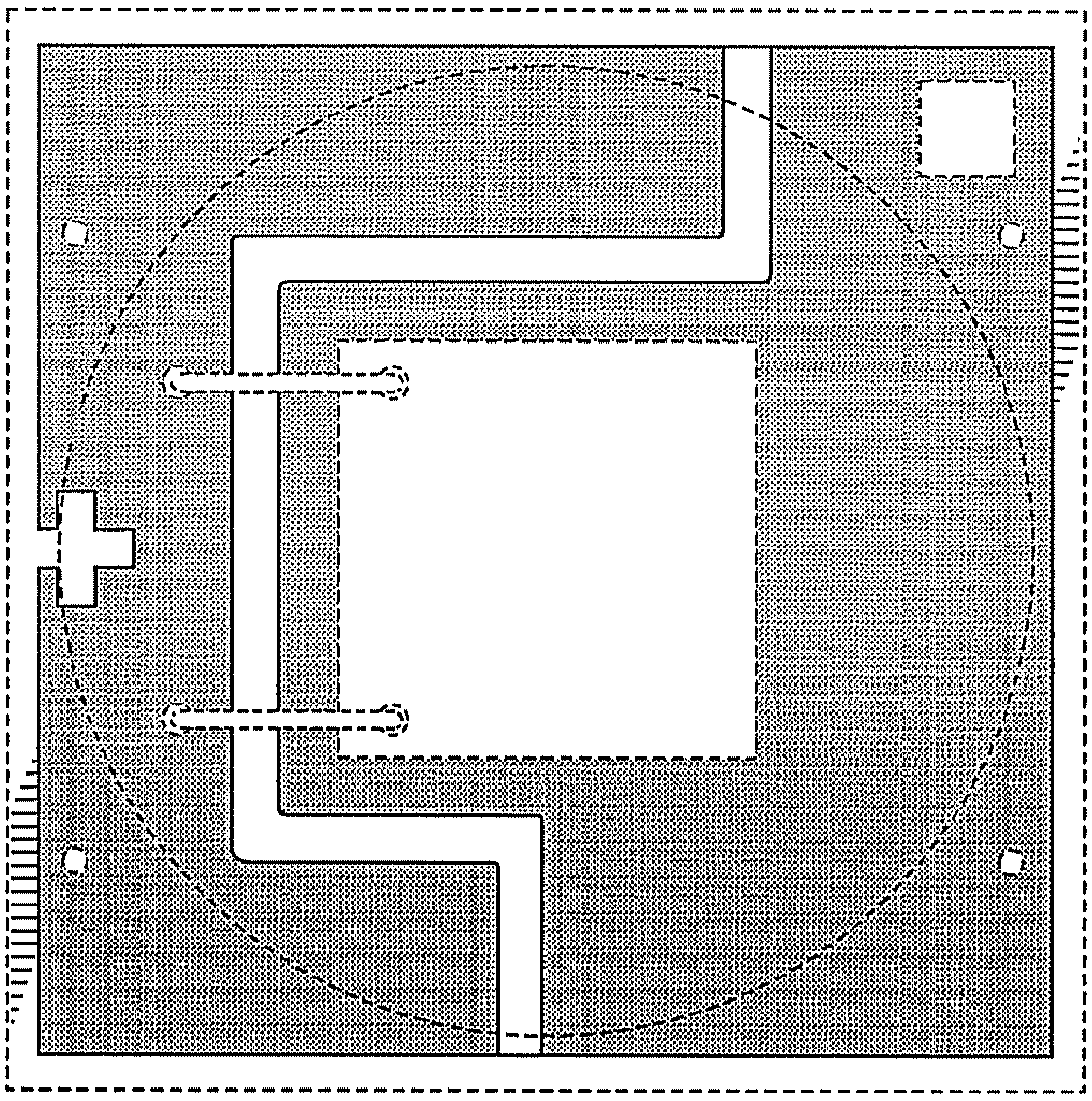


FIG. 37

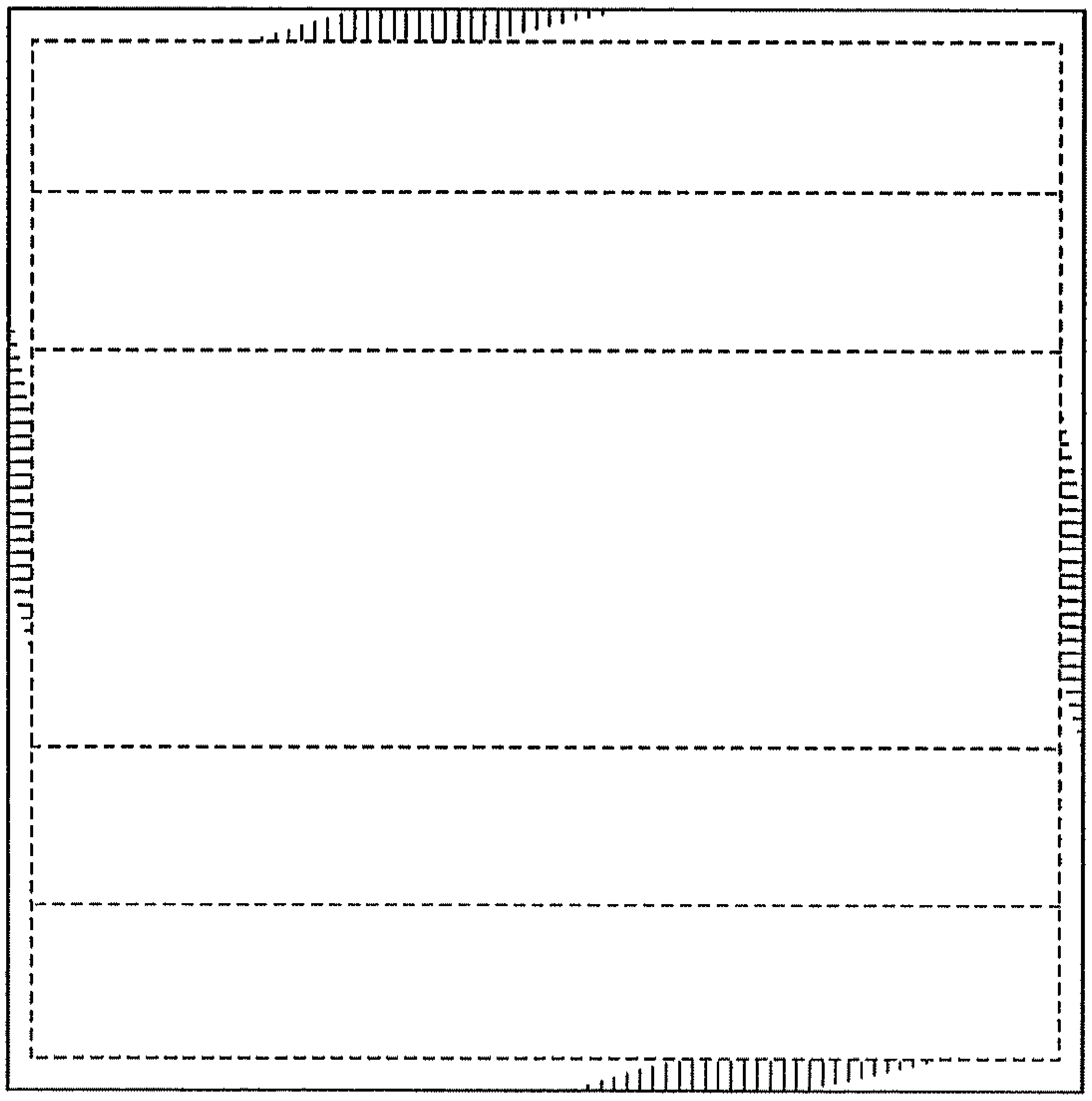
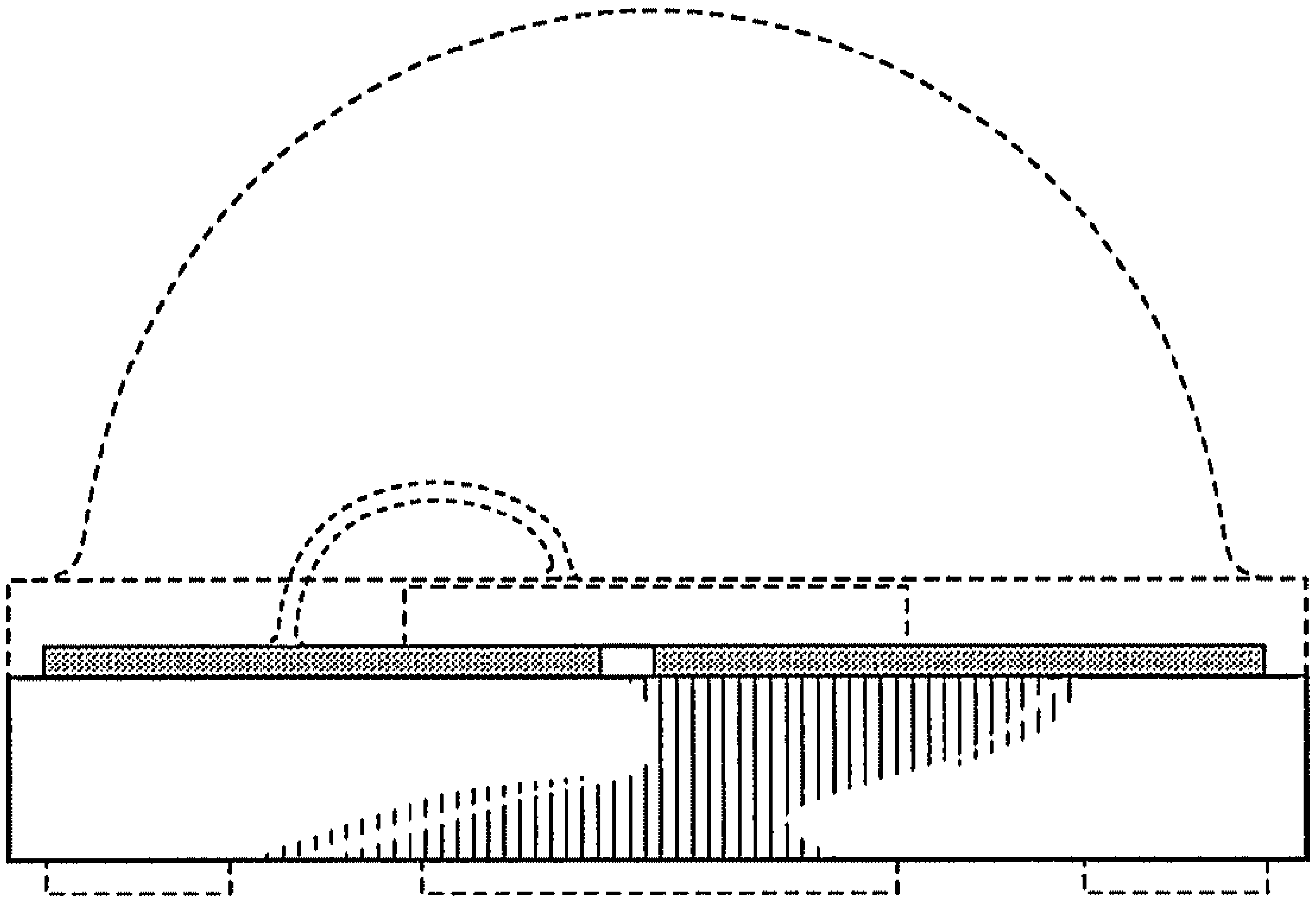


FIG. 38



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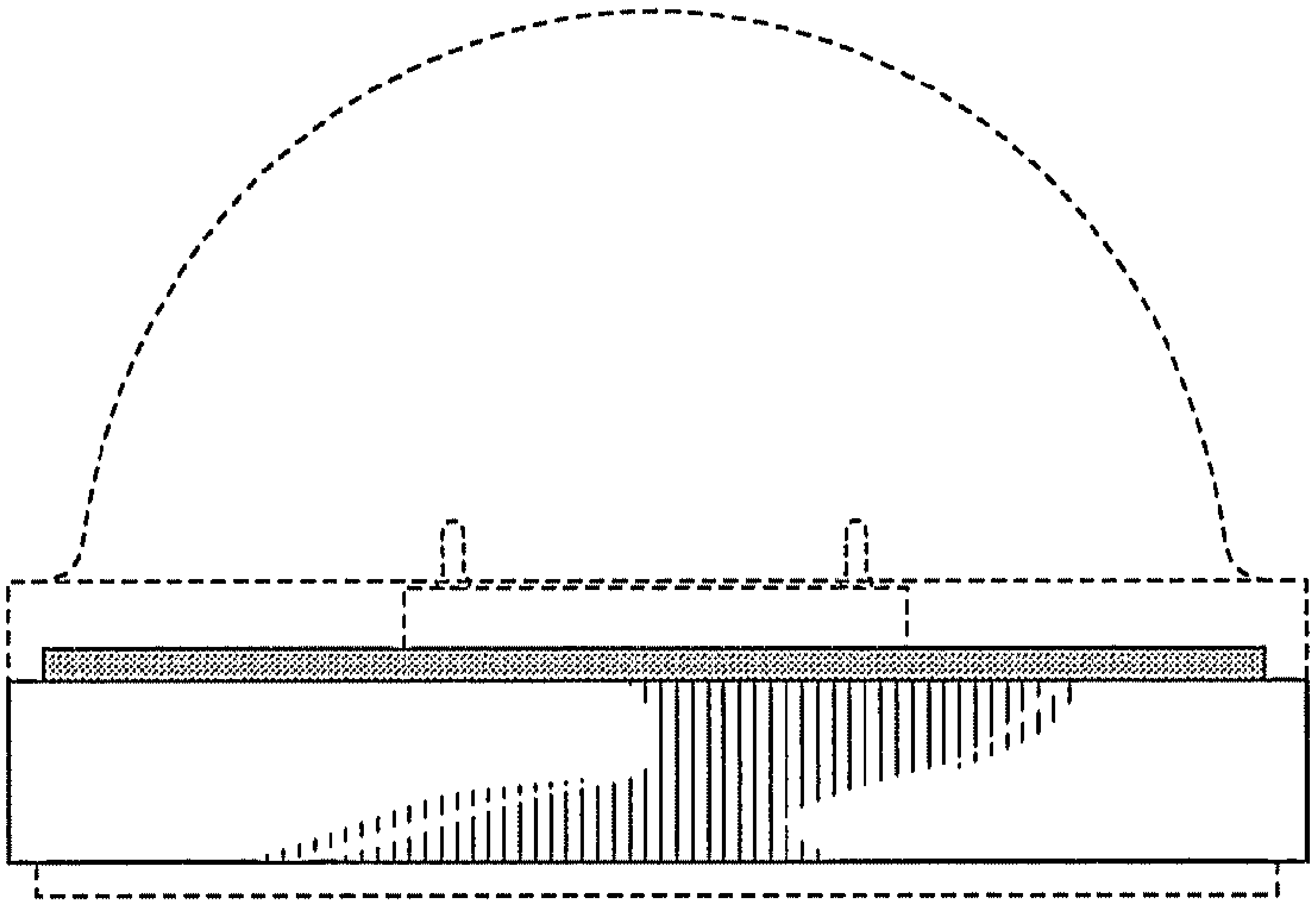

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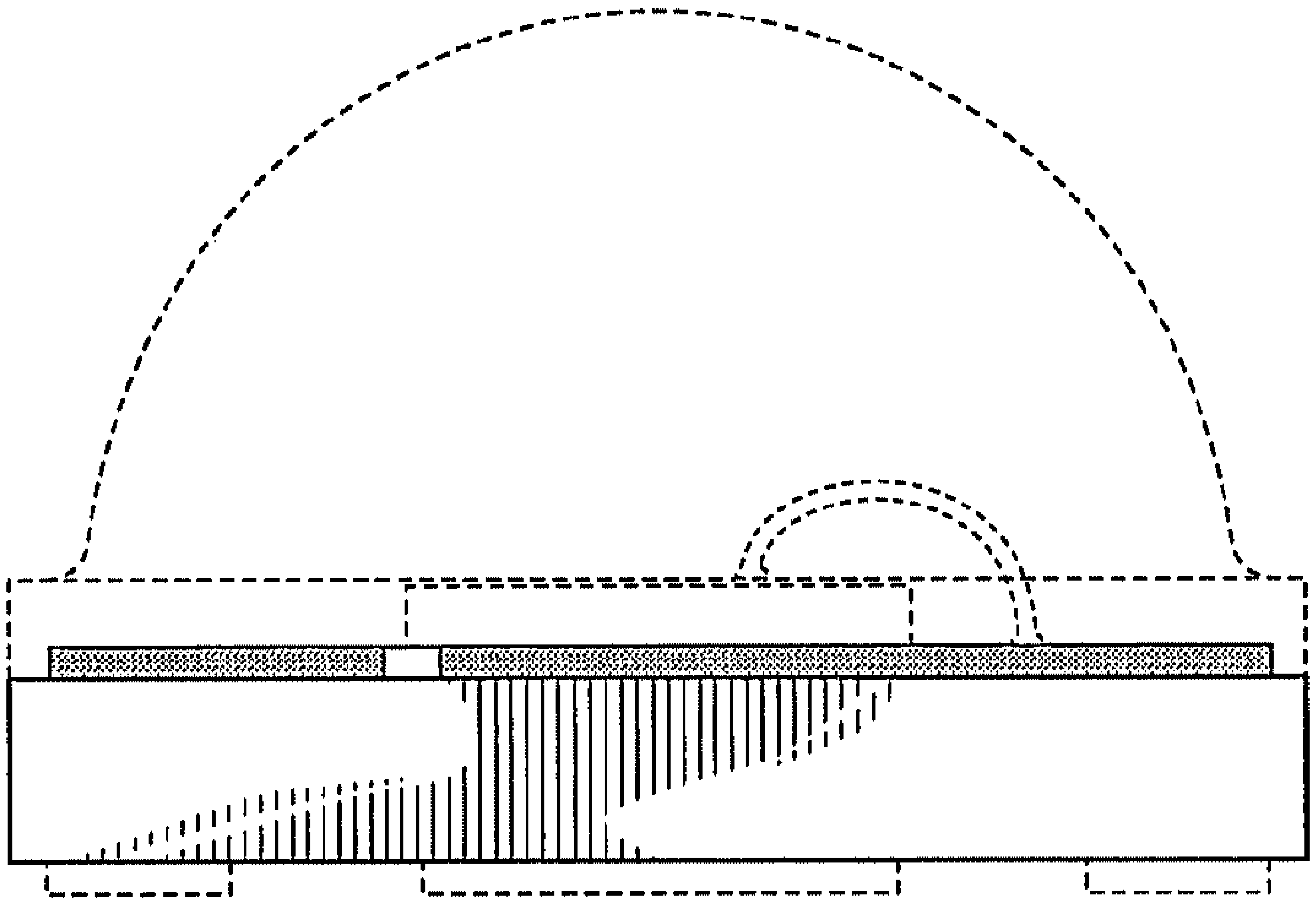

FIG. 41

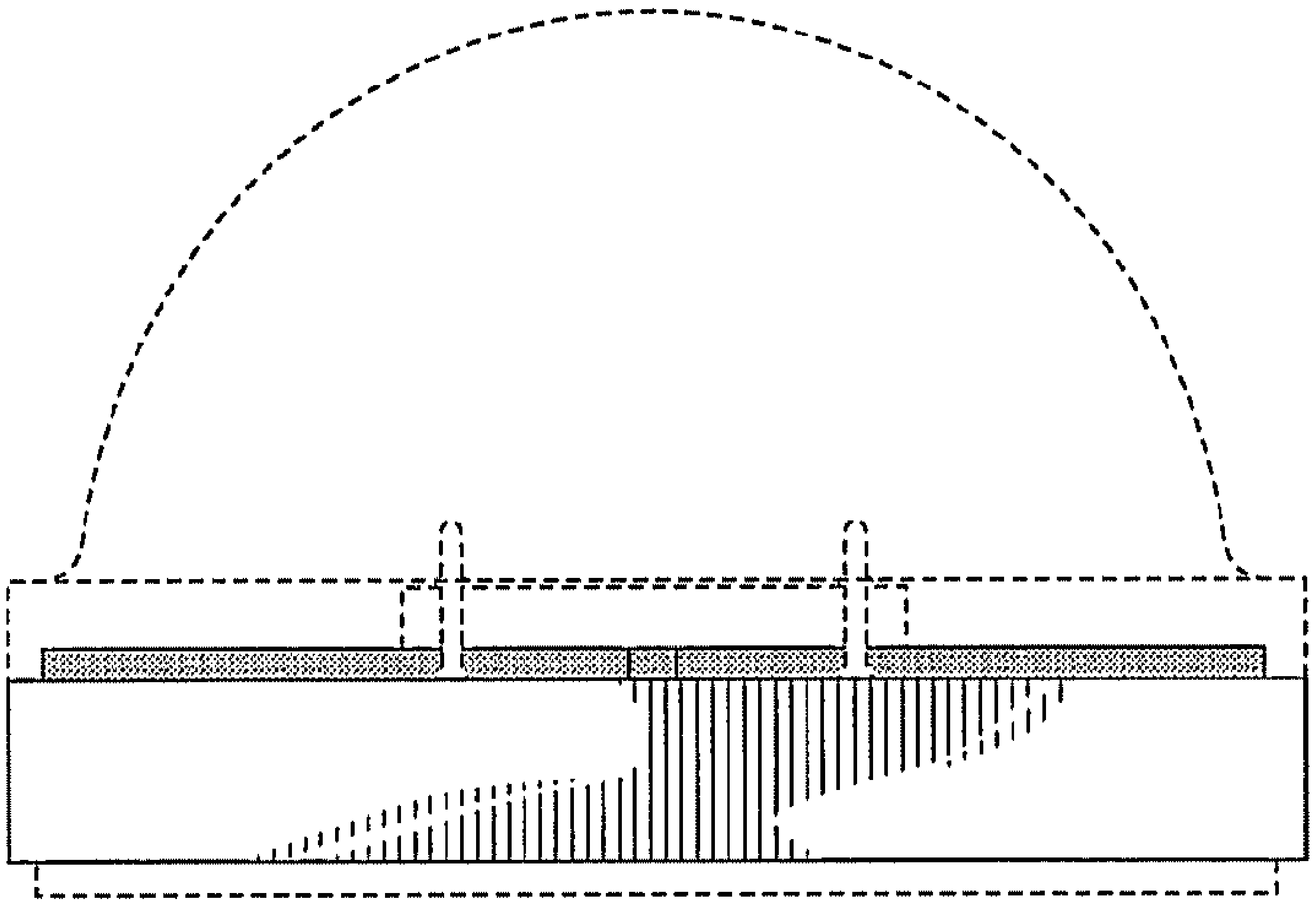

FIG. 42